





Pak-Austria Fachhochschule: Institute of Applied Sciences & Technology, Haripur

KHYBER PAKHTUNKHWA

REQUEST FOR PROPOSAL (RFP) FOR

"Supply, Installation & Commissioning of Labs Equipment for Sino-Pak Center for Artificial Intelligence (SPCAI)"

Submission of Bids: Weekday, January 09, 2024 @ 12:00 noon

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Section 1. Letter of Invitation

The Pak-Austria Fachhochschule: Institute of Applied Sciences & Technology (PAF- IAST), Haripur invites sealed bids from interested firms for the "Supply, Installation & Commissioning of Labs Equipment for Sino-Pak Center for Artificial Intelligence (SPCAI)" under the following Lots.

| Lot.# | Lot Descriptions | | | |
|--------|--|--|--|--|
| Lot 1: | Customized Multi-copters Agile Drone | | | |
| Lot 2: | Customized Multi-copters Carrier Drone | | | |
| Lot 3: | Drone Swarm and Safety Net | | | |
| Lot 4: | Field Robotics Lab | | | |
| Lot 5: | IoT, Sensors and IT Equipment | | | |
| Lot 6: | Embedded Systems | | | |
| Lot 7: | Furniture for Labs - Chairs | | | |
| Lot 8: | Intelligent Biomedical Lab | | | |
| Lot 9: | Computer Vision Lab | | | |

The bidder must be registered and duly recognized in Pakistan and be registered with FBR; possess Manufacturer's status or Distributor/ Dealer status with authorization from Manufacturer/ Principal specific for this tender, with sufficient financial, technical, and human resources to take up the task assigned and complete the same within prescribed time limit on the finalization of contract with PAF- IAST.

Tender document containing instructions to bidders covering definitions, introduction/background of the Project, scope of work, general terms and conditions, and special terms, procedure for submission of bids, opening of bid, evaluation criteria, and other related information, can be obtained against a written request on company's letterhead, from Pak-Austria Fachhochschule: INSTITUTE of Applied Sciences & Technology, Haripur — Pakistan. Cost of the document is Rs. 500/- Non-refundable (Stationery charges) for each LOT separately. Tender document can also be downloaded from www.paf-iast.edu.pk/ free of cost, however, the Bid should also be submitted along with Pay Order/ Demand Draft of Rs. 500/- (Stationery Charges). No bid will be accepted without the Tender Document fee.

Bidder(s) interested in participating in the tender process are advised to submit their Bid Proposal(s), along with the Earnest Money amounting 2% of their Bid Value in the shape of CDR, in accordance with the instructions in this tender document. Bid Proposal(s) must reach PAF-IAST, Haripur on Tuesday January 09, 2024 @ 12:00 noon. Any late Bid(s) shall not be accepted and returned unopened. Accepted Bids will be opened on the same day at 12:30 hrs, in presence of bidders who chose to attend. In case of sudden holiday on bid opening day, bids will be opened on next working day. The Tender shall be executed in accordance with PPRA Rule 36(b) "Single Stage, Two Envelope Procedure". This advertisement is also available on PAF: IAST and PPRA websites http://www.paf-iast.edu.pk/ http://www.ppra.gov.pk.

Project Director

Sino-Pak Center for Artificial Intelligence (SPCAI)

Pak-Austria Fachhochschule: Institute of Applied Sciences & Technology (PAF-IAST), Mang

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Section 2. Instruction to Bidders (ITB)

| A CENEDAL TERMS | |
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| A. GENERAL TERMS 1. Introduction | 1.1 Bidders shall adhere to all the requirements of this ITB, including any |
| | amendments made in writing by PAF-IAST. This ITB will be governed under Clause 36(b) "Single Stage, Two Envelope Procedure" of Public Procurement Regulatory Authority. |
| | 1.2 Any Bid submitted will be regarded as an offer by the Bidder and does not constitute or imply the acceptance of the Bid by PAF-IAST. The Institute is under no obligation to award a contract to any Bidder as a result of this ITB. |
| | 1.3 PAF-IAST reserves the right to cancel the procurement process at any stage without any liability of any kind for PAF-IAST, upon notice to the bidders or publication of cancellation notice on PAF- IAST website. |
| 2. Fraud & Corruption, Gifts and Hospitality | 2.1 PAF-IAST strictly enforces a policy of zero tolerance on proscribed practices, including fraud, corruption, collusion, unethical or unprofessional practices, and obstruction of PAF-IAST vendors and requires all bidders/ vendors observe the highest standard of ethics during the procurement process and contract implementation. |
| | 2.2 Bidders/ vendors shall not offer gifts or hospitality of any kind to PAF-IAST staff members including recreational trips to sporting or cultural events, theme parks or offers of holidays, transportation, or invitations to extravagant lunches or dinners. |
| | 2.3 In pursuance of this policy, PAF-IAST: |
| | (a) Shall reject a bid if it determines that the selected bidder has engaged in any corrupt or fraudulent practices in competing for the contract in question; |
| | (b) Shall declare a vendor ineligible, either indefinitely or for a stated period, to be awarded a contract if at any time it determines that the vendor has engaged in any corrupt or fraudulent practices in competing for, or in executing a PAF- IAST contract; or counseling or canvassing staff or elected representatives; or engaging in collusion with other bidders. |
| 3. Eligibility | 3.1 A Bidder should not be suspended, debarred, or otherwise identified as ineligible by any Government/ Semi-government/ or any other international Organization. Bidders are therefore required to disclose to PAF-IAST whether they are subject to any sanction or temporary suspension imposed by these organizations. |
| | 3.2 It is the Bidder's responsibility to ensure that its employees, sub-contractors, service providers, suppliers and/ or their employees meet the eligibility requirements as established by PAF-IAST. |
| 4. General Terms | 4.1 The Bidder should be registered with Sales Tax and Income Tax Department. |
| | 4.2 The Bidder should have not been blacklisted by any Government/ semi Government organization. |
| | 4.3 There should be no litigation against the bidder/ firm. |
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| B. PREPARATION OF BID | 5 |
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| 5. General Considerations | 5.1 In preparing the Bid, the Bidder is expected to examine the ITB in detail. Material deficiencies in providing the information requested in the ITB may result in rejection of the Bid. |
| | 5.2 The Bidder will not be permitted to take advantage of any errors or omissions in the ITB. Should such errors or omissions be discovered, the Bidder must notify the Project Director, SPCAI accordingly. |
| 6. Cost of Preparation of Bid | 6.1 The Bidder shall bear all costs related to the preparation and/ or submission of the Bid, regardless of whether its Bid is selected or not. PAF-IAST shall not be responsible or liable for those costs, regardless of the conduct or outcome of the procurement process. |
| 7. Language | 7.1 The Bid, as well as any, and all related correspondence exchanged by the Bidder and PAF- IAST, shall be written in the language(s) specified in the BDS. |
| 8. Documents Comprising the Bid | 8.1 The Bid shall comprise of the following documents and related forms of which details are provided in the BDS. All pages of the Bid shall be signed, stamped and properly paginated. |
| | Returnable Forms as referred in Section 6 shall be properly filled in Ink or Typed. Forms filled in using a pencil shall not be considered and substantiate the annulment of the Bid Proposal. |
| | Documents Establishing the Eligibility and Qualifications of the Bidder; Bid covering Technical Specifications in detail, and covering Price Schedule; Bid Security, if required by BDS; e) Any attachments and/or appendices to the Bid. |
| 9.Documents Establishing the Eligibility and Qualifications | 9.1 The Bidder shall furnish documentary evidence of its status as an eligible and qualified supplier, using the Forms provided under Section 6 and providing documents required in those forms. In order to award a contract to a Bidder, its qualifications must be documented to PAF-IAST's satisfaction. |
| 10. Technical Bid Format and Content | 10.1 The Bidder is required to submit a Bid using the Standard Forms and templates provided in Section 6 of the ITB. |
| | 10.2 Samples of items, when required as per Section 5, shall be provided within the time specified and unless otherwise specified by the Purchaser, at no expense to the Institute. If not destroyed by testing, samples will be returned at Bidder's request and expense, unless otherwise specified. |
| | 10.3 When applicable and required in Section 5, the Bidder shall describe the necessary training program available for the maintenance and operation of the equipment offered as well as the cost to the Institute. Unless otherwise specified, such training as well as training materials shall be provided in the language of the Bid as specified in the BDS. |
| | 10.4 When applicable and required in Section 5, the Bidder shall certify the availability of spare parts for a period of at least five (5) years from date of delivery, or as otherwise specified in this ITB. |
| 11. Price Schedule | 11.1 The Price Schedule shall be prepared using the Forms provided in Section 6 of the ITB and taking into consideration the requirements in the ITB. |
| | 11.2 Any requirement described in this ITB but not priced in the Price Schedule, shall be assumed to have been included in the prices of other activities or items, as well as in the final total price. |

| 12. Bid Security | 12.1 | A Bid Security shall be provided in the amount and form indicated in the BDS. The Bid Security shall be valid for the duration as referred in BDS. |
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| | 12.2 | The Bid Security shall be included along with the Bid. If Bid Security not found in the Bid, the Bid shall be rejected. |
| | 12.3 | If the Bid Security amount or its validity period is found to be less than what is required, PAF-IAST shall reject the Bid. |
| | 12.4 | In the event an electronic submission is allowed in the BDS, Bidders shall include a copy of the Bid Security in their bid and the original of the Bid Security must be sent via courier or hand delivery as per the instructions in BDS. |
| | 12.5 | The Bid Security will be forfeited by PAF-IAST, and the Bid rejected, in the event of any, or combination, of the following conditions: |
| | | a) If the Bidder withdraws its offer during the period of the Bid Validity specified in the BDS, or; |
| | | b) In the event the successful Bidder fails: |
| | | i. to sign the Contract after PAF-IAST has issued an award; or |
| | | ii. to furnish the Performance Security, insurances, or other documents that PAF-IAST may require as a condition precedent to the effectivity of the contract that may be awarded to the Bidder. |
| 13. Currencies | 13.1 | All prices shall be quoted in the currency indicated in the BDS. Where prices are quoted in different currencies, for the purposes of comparison: |
| | | PAF-IAST will convert the currency quoted into the currency indicated in BDS, in accordance with the prevailing Inter Bank rate of exchange on the last day of submission of Bids; and |
| | | b) In the event that PAF-IAST selects a Bid for award that is quoted in a currency different from the preferred currency in the BDS, PAF-IAST shall reserve the right to award the contract in the currency of PAF-IAST's preference, using the conversion method specified above. |
| 14. Joint Venture, Consortium or Association | 14.1 | If the Bidder is a group of legal entities that will form or have formed a Joint Venture (JV), Consortium or Association for the Bid, they shall confirm in their Bid that: (i) they have designated one party to act as a lead entity, duly vested with authority to legally bind the members of the JV, Consortium or Association jointly and severally, which shall be evidenced by an intent letter or an Agreement among the legal entities duly notarized, and submitted with the Bid; and (ii) if they are awarded the contract, the contract shall be entered into, by and between PAF-IAST and the designated lead entity, who shall be acting for and on behalf of all the member entities comprising the joint venture. |
| | 14.2 | After the Deadline for Submission of Bid, the lead entity identified to represent the JV, Consortium or Association or any change in the constitution of the JV, Consortium or Association shall not be altered without the prior written consent of PAF-IAST/ Procurement Committee. |
| I | 14.3 | The lead entity and the member entities of the JV, Consortium or Association shall abide by the provisions of Clause 15 herein in respect of submitting only one Bid. |
| | 14.4 | The description of the organization of the JV, Consortium or Association must clearly define the expected role of each of the entities in the joint venture in delivering the requirements of the ITB, both in the Bid and the JV, Consortium or Association Agreement or Intent Letter. All entities that comprise the JV, Consortium or Association shall be cumulatively subject to the eligibility and |

| | | technical qualification assessment by PAF-IAST as defined in Section 4: Evaluation Criteria. |
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| | 14.5 | A JV, Consortium or Association in presenting its track record and experience should clearly differentiate between: |
| | | a) Those that were undertaken together by the JV, Consortium or Association; and |
| | | b) Those that were undertaken by the individual entities of the JV, Consortium or Association. |
| | 14.6 | Previous contracts completed by individual experts working privately but who are permanently or were temporarily associated with any of the member firms cannot be claimed as the experience of the JV, Consortium or Association or those of its members, but should only be claimed by the individual experts themselves in their presentation of their individual credentials. |
| 15. Only One Bid | 15.1 | The Bidder (including the individual members of any Joint Venture) shall submit only one Bid, either in its own name or as part of a Joint Venture. |
| | 15.2 | Bids submitted by two (2) or more Bidders shall all be rejected if they are found to have any of the following: |
| | | they have at least one controlling partner, director or shareholder in common; or |
| | | b) any one of them receive or have received any direct or indirect subsidy from the other/s; or |
| | | c) they have the same legal representative for purposes of this ITB; or |
| | | d) they are subcontractors to each other's Bid, or a subcontractor to one Bid also submits another Bid under its name as lead Bidder; or some key personnel proposed to be in the team of one Bidder participates in more than one Bid received for this ITB process. This condition relating to the personnel, does not apply to subcontractors being included in more than one Bid. |
| 16. Bid Validity Period | 16.1 | Bids shall remain valid for the period specified in the BDS, commencing on the Deadline for Submission of Bids. A Bid valid for a shorter period may be rejected by PAF-IAST and rendered non-responsive. |
| | 16.2 | During the Bid validity period, the Bidder shall maintain its original Bid without any change, including the availability of the Key Personnel. |
| 17. Extension of Bid Validity Period | 17.1 | In exceptional circumstances, prior to the expiration of the Bid validity period, PAF-IAST may request Bidders to extend the period of validity of their Bids. The request and the responses shall be made in writing and shall be considered integral to the Bid. |
| | 17.2 | If the Bidder agrees to extend the validity of its Bid, it shall be done without any change to the original Bid. |
| | 17.3 | The Bidder has the right to refuse to extend the validity of its Bid, in which case, the Bid shall not be further evaluated. |
| 18. Clarification on ITB (from the Bidders) | 18.1 | Bidders may request clarifications on any of the ITB documents no later than the date indicated in the BDS. Any request for clarification must be sent in writing in the manner indicated in the BDS. If inquiries are sent other than specified channel, even if they are sent to a PAF-IAST staff member, PAF-IAST shall have no obligation to respond or confirm that the query was officially received. |

| | 18.2 | PAF-IAST will provide the responses to clarifications through the method specified in the BDS. |
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| | 18.3 | PAF-IAST shall endeavor to provide responses to clarifications in an expeditious manner, but any delay in such response shall not cause an obligation on the part of PAF-IAST to extend the submission date of the Bids, unless PAF-IAST deems that such an extension is justified and necessary. |
| 19. Amendment in ITB | 19.1 | At any time prior to the deadline of Bid submission, PAF-IAST may for any reason, such as in response to a clarification requested by a Bidder, modify the ITB in the form of an amendment to the ITB. Amendments will be made available to all prospective bidders. |
| | 19.2 | If the amendment is substantial, PAF-IAST may extend the Deadline for submission of Bid to give the Bidders reasonable time to incorporate the amendment into their Bids. |
| 20. Alternative Bids | 20.1 | Unless otherwise specified in the BDS, alternative Bids shall not be considered. If submission of alternative Bid is allowed by BDS, a Bidder may submit an alternative Bid, but only if it also submits a Bid conforming to the ITB requirements. Where the conditions for its acceptance are met, or justifications are clearly established, PAF-IAST reserves the right to award a contract based on an alternative Bid. |
| | 20.2 | If multiple/ alternative bids are being submitted, they must be clearly marked as "Main Bid" and "Alternative Bid" |
| 21. Pre-Bid Conference | 21.1 | When appropriate, a pre-bid conference may be conducted at the date, time and location specified in the BDS. All Bidders are encouraged to attend. Non-attendance, however, shall not result in disqualification of an interested Bidder. Minutes of the Bidder's conference will be disseminated on the procurement website and/ or shared by email as specified in the BDS. No verbal statement made during the conference shall modify the terms and conditions of the ITB, unless specifically incorporated in the Minutes of the Bidder's Conference or issued/ posted as an amendment to ITB. |
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C. SUBMISSION AND OPENING OF BIDS

22. Bid Proposal Submission

- 22.1 The Bidder shall submit a duly signed and numbered all pages of the complete Bid in an Envelope sealed and marked as per ITB 22.6, and in accordance with **PPRA Rule 36(b)**.
- 22.2 The Outer Envelope should contain Two (02) separate sealed envelopes, one of which comprising the Forms (A F) and supporting documents in accordance with requirements in the BDS, shall be marked as "Technical Proposal". Whereas, the other envelope containing the Form G: Price Schedule Form shall be marked as "Financial Proposal".
- The Bid Security as referred in BDS must be placed in the "Financial Proposal" but in duly sealed envelope and marked as "Bid Security". However, an Affidavit stating that the Bid Security (without indicating the amount) has been placed in the Financial Proposal, should be enclosed in "Technical Proposal". Bid Security envelope will be opened with financial proposal of Technically qualified bidders.

Bid can be delivered either personally, or by courier as specified in the BDS.

22.5 The Bid shall be signed by the Bidder or person(s) duly authorized to commit the Bidder. The authorization shall be communicated through a document evidencing such authorization issued by the legal representative of the bidding entity, or a Power of Attorney, accompanying the Bid. There should not be errors and/ or over-writings. Corrections (if any) should be made clearly and initialed with dates. 22.6 Bidders must be aware that the mere act of submission of a Bid, in and of itself, implies that the Bidder fully accepts the General Contract Terms and Conditions. 22.7 Hard copy submission by courier or hand delivery allowed or specified in the BDS shall be governed as follows: a) The signed Bid shall be marked "Original", and its copies marked "Copy" as appropriate. The number of copies is indicated in the BDS. All copies shall be made from the signed original only. If there are discrepancies between the original and the copies, the original shall prevail. (b) The Bid Proposals must be sealed and submitted in an envelope, which shall: i. Bear the name of the Bidder; ii. Be addressed to PAF - IAST as specified in the BDS; and iii. Bear a warning not to open before the time and date for Bid opening as specified in the BDS. If the envelope with the Bid is not sealed and marked as required, PAF-IAST shall assume no responsibility for the misplacement, loss, or premature opening of the Bid. 23. Deadline for Submission 23.1 Complete Bids must be received by PAF-IAST in the manner, and no later than the of Bids and Late Bids date and time, specified in the BDS. PAF-IAST shall only recognize the actual date and time that the bid was received by PAF-IAST. 23.2 PAF-IAST shall not consider any Bid that is received after the deadline for the submission of Bids. 24. Withdrawal, 24.1 A Bidder may withdraw, substitute or modify its Bid after it has been submitted at Substitution, and any time prior to the deadline for submission. Modification of Bids 24.2 A bidder may withdraw, substitute or modify its Bid by sending a written notice to PAF- IAST, duly signed by an authorized representative, including a Power of Attorney. The corresponding substitution or modification of the Bid must accompany the respective written notice. All notices must be submitted in the same manner as specified for submission of Bids, by clearly marking them as "WITHDRAWAL" "SUBSTITUTION," or "MODIFICATION." 24.3 Bids requested to be withdrawn shall be returned unopened to the Bidders, except if the bid is withdrawn after the bid has been opened. 25. Bid Opening 25.1 The Procurement Committee of PAF- IAST will open the Bid in the presence of Bidders' representative(s) who choose to attend. 25.2 The Bidders' names, modifications, withdrawals, the condition of the envelope labels/ seals, the number of folders/ files and all other such other details as PAFIAST may consider appropriate, will be announced at the opening. No Bid shall be rejected at the opening stage, except for late submissions, in which case, the Bid shall be returned unopened to the Bidders. 25.3 In case of public holiday on bid opening day, bids will be opened on next working day.

| D. EVALUATION OF BIDS | S |
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| 26. Confidentiality | 26.1 Information relating to the examination, evaluation, and comparison of Bids, and the recommendation of contract award, shall not be disclosed to Bidders, even after publication of the contract award. |
| | 26.2 Any effort by a Bidder to influence PAF-IAST in the examination, evaluation and comparison of the Bids or contract award decisions may, at PAF-IAST's decision, result in the rejection of its Bid and may subsequently be subject to consequences. |
| 27. Preliminary Examination | 27.1 PAF-IAST shall examine the Bids to determine whether they are complete with respect to minimum documentary requirements, whether the documents have been properly signed, and whether the Bids are generally in order, among other indicators that may be used at this stage. PAF-IAST reserves the right to reject any Bid at this stage. |
| 28. Evaluation of Eligibility and Technical | 28.1 Eligibility and Technical Qualification of the Bidder will be evaluated against the Minimum Eligibility/ Qualification requirements specified in the Section 4: Evaluation Criteria. |
| Qualification | 28.2 In general terms, Bidders that meet the following criteria may be considered qualified: |
| | They are not included in the list of blacklisted or barred companies published on PPRA website, any federal or provincial government department; |
| | They have a good financial standing and have access to adequate financial resources to perform the contract and all existing commercial commitments, |
| | They have the necessary experience, technical expertise, production capacity, quality certifications, quality assurance procedures and other resources applicable to the supply of goods and/ or services required; |
| | d) They are able to comply fully with the General Terms and Conditions of Contract; |
| | e) They do not have a consistent history of court/ arbitral award decisions against the Bidder; and |
| | f) They have a record of timely and satisfactory performance with their clients. |
| 29. Evaluation of Bid Proposals | 29.1 The evaluation team shall review and evaluate the Bids on the basis of their responsiveness to the Schedule of Requirements and Technical Specifications and other documentation provided, applying the procedure indicated in the BDS and other ITB documents. When necessary, and if stated in the BDS, PAF- IAST may invite technically responsive bidders for a presentation related to their Bids. The conditions for the presentation shall be provided in the bid document where required. |
| 30. Due diligence | 30.1 PAF- IAST reserves the right to undertake a due diligence exercise, aimed at determining to its satisfaction, the validity of the information provided by the Bidder. Such exercise shall be fully documented and may include, but need not be limited to, all or any combination of the following: a) Verification of accuracy, correctness and authenticity of information provided by the Bidder; b) Validation of extent of compliance to the ITB requirements and evaluation criteria based on what has so far been found by the evaluation team; c) Inquiry and reference checking with Government entities with jurisdiction on the Bidder, or with previous clients, or any other entity that may have done business with the Bidder; d) Inquiry and reference checking with previous clients on the performance on on-going or completed contracts, including physical inspections of previous works, as deemed necessary; |

| | e) Physical inspection of the Bidder's offices, branches or other places where business transpires, with or without notice to the Bidder; f) Other means that PAF-IAST may deem appropriate, at any stage within the selection process, prior to declaring the Bidder as Qualified. |
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| 31. Clarification of Bids | To assist in the examination, evaluation and comparison of Bids, PAF- IAST may, at its discretion, request any Bidder for a clarification of its Bid. |
| | PAF- IAST's request for clarification and the response shall be in writing and no change in the prices or substance of the Bid shall be sought, offered, or permitted, except to provide clarification, and confirm the correction of any arithmetic errors discovered by PAF-IAST in the evaluation of the Bids in accordance with the ITB. |
| | Any unsolicited clarification submitted by a Bidder in respect to its Bid, which is not a response to a request by PAF-IAST, may not be considered during the review and evaluation of the Bids. |
| 32. Responsiveness of Bid | PAF-IAST's determination of a Bid's responsiveness will be based on the contents of the bid itself. A substantially responsive Bid is one that conforms to all the terms, conditions, specifications and other requirements of the ITB without material deviation, reservation, or omission. |
| | 32.2 If a bid is not substantially responsive, it may be rejected by PAF-IAST and may not subsequently be made responsive by the Bidder by correction of the material deviation, reservation, or omission. |
| 33. Right to Accept, Reject, Any or All Bids | PAF-IAST reserves the right to accept or reject any proposal in response to the ITB, to render any or all of the proposals as non-responsive, and to reject all Proposals in response to the ITB at any time prior to award of contract, while assigning the reason(s) thereof. |
| | 33.2 PAF- IAST shall not be obliged to award the contract to the lowest priced offer. |
| 34. Nonconformities, Reparable Errors and Omissions | Provided that a Bid is substantially responsive, PAF-IAST may waive any nonconformities or omissions in the Bid that, in the opinion of PAF-IAST, do not constitute a material deviation. |
| | 34.2 PAF-IAST may request the Bidder to submit the necessary information or documentation, within a reasonable period, to rectify nonmaterial nonconformities or omissions in the Bid related to documentation requirements. Such omission shall not be related to any aspect of the price. Failure of the Bidder to comply with the request may result in the rejection of its Bid. |
| | 34.3 For the Price Schedule that are submitted, PAF-IAST shall check and correct arithmetical errors as follows: |
| | a) if there is a discrepancy between the unit price and the line item total that is obtained by multiplying the unit price by the quantity, the unit price shall prevail and the line item total shall be corrected, unless in the opinion of PAF- IAST there is an obvious misplacement of the decimal point in the unit price; in which case, the line item total as quoted shall govern and the unit price shall be corrected; |

| | b) if there is an error in a total corresponding to the addition or subtraction of subtotals, the subtotals shall prevail and the total shall be corrected; and | |
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| | c) if there is a discrepancy between words and figures, the amount in words shall prevail, unless the amount expressed in words is related to an arithmetic error, in which case the amount in figures shall prevail. | |
| | 34.4 If the Bidder does not accept the correction of errors made by PAF- IAST, its Bid shall be rejected. | |
| 35. Bidder Grievance | 35.1 PAF- IAST's grievance readdress procedure provides an opportunity for appeal to those persons or firms not awarded a contract through a competitive procurement process. In the event that a Bidder believes that it was not treated fairly, the Bidder may lodge a complaint to the PAF-IAST's Grievance Readdress Committee. | |
| E. AWARD OF CONTRACT | | |
| 36. Evaluation | PAF-IAST will conduct the evaluation solely on the basis of response to this tender received from the firms. | |
| | 36.2 Evaluation shall be undertaken in the following steps: a) Preliminary Examination including Technical Specifications and other compliances | |
| | Arithmetical check and ranking of bidders who passed preliminary examination by price. | |
| | c) Evaluation of prices | |
| | 36.3 Price comparison shall be based on the landed price, including transportation, insurance and the total cost of ownership (including spare parts, consumption, installation, commissioning, training, special packaging, etc., where applicable) | |
| 37. Integrity Pact | 37.1 Bidders will also be required to submit a signed Integrity Pact on a stamp paper of appropriate value as part of their response. The text of Integrity Pact is available at Annex – I. | |
| 38. Award Criteria | 38.1 Prior to expiration of the period of Proposal validity, PAF-IAST shall award the contract to the Bidder that is found to be responsive to the requirements of the Technical Specifications and has offered the lowest price. | |
| | PAF-IAST shall not be obliged to award the contract to the lowest priced offer, if the response is found deficient to the Technical Specifications and other compliances. | |
| | In case of tie in Financial Bid Value, the Contract will be awarded to the bidder having more closest match to the Technical Specifications. | |
| 39. Contract Signing | 39.1 After the approval of any Work Award, a Contract Agreement on the stamp paper of appropriate value, shall be executed by PAF-IAST with Selected Bidder (i.e. Contractor) within 15 days from the date of issuance of LoI (Letter of Intent)/ Work Order. | |
| | 39.2 Failure to signing of Contract Agreement by the selected Bidder Firm with PAFIAST within the stipulated time may constitute sufficient grounds for the annulment of the award, and forfeiture of the Bid Security, if any, and on which event, PAF- IAST may award the Contract to the Second highest rated or call for new Proposals. | |

| 40. Right to Vary quantity at the Time of Award | 40.1 At the time of award of Contract, PAF-IAST reserves the right to vary the quantity of goods and/ or services, without any change in the unit price or other terms and conditions. | | |
|---|---|--|--|
| 41. Sample draft Contract | 41.1 A sample draft Contract to be signed, containing applicable General Terms and Conditions can be found at Annex – II. | | |
| 42. Performance Security | 2.1 A performance security, if required in the BDS, shall be provided in the amount specified in BDS, well prior to the Contract signing by both parties. Where a performance security is required, the receipt of the performance security by PAFIAST shall be a condition for rendering the contract effective. | | |
| 43. Bank Guarantee for Advanced Payment | 43.1 No Payment will be released in advance. | | |
| 44. Liquidated Damages | 44.1 PAF-IAST shall apply Liquidated Damages for the damages and/ or risks caused to PAF-IAST resulting from the Contractor's delays or breach of its obligations as per Contract. | | |
| | a) In case of delay, the Procurement Committee, PAF-IAST reserves the right to impose a penalty not exceeding 10% of the total amount of the Contract Value at the rate as referred in the Sample Contract at Annexure – II. | | |
| | b) If the Contractor fails to complete work as per PAF-IAST requirement, the Rector, PAF-IAST reserves the right to reject it altogether or impose a penalty not exceeding 50% of the total amount of the Contract. | | |
| | c) If the Contractor fails to provide supplies/ services as per PAF-IAST requirements, PAF-IAST may forfeit his earnest money as well as Performance Security, and the work will be done at the risk and cost of Contractor. d) In case of any dispute, matter will be referred to Rector, PAF-IAST whose decision will be binding on both the parties. | | |
| 45. Force Majeure | 45.1 "Force Majeure" means an event which is beyond the reasonable control of a party and which makes a party's performance of its obligations under the Purchase Order/ Work Order/ Contract impossible or so impractical as to be considered impossible under the circumstances, and includes, but is not limited to, War, Riots, Storm, Flood or other industrial actions (except where such strikes, lockouts or other industrial issues are within the power of the party invoking Force Majeure), confiscation or any other action by Government agencies. In all disputes between the parties as to matters arising pursuant to this Purchase Order/ Work Order/ Contract, the dispute will be referred to Project Director, SPCAI whose decision will be final. | | |
| 46. Delivery of Goods | 46.1 Contractor will be required to deliver the goods as per the Delivery Schedule referred in BDS without claiming any additional cost to the PAF-IAST at the designated site(s) and in quantities as referred in the Contract. | | |
| 47. Payment Provisions | 47.1 Payment may be made through LC (Letter of Credit) which will be Open by PAF-IAST within 30 days after signing the Contract. However, Payment will be made only upon PAF-IAST's acceptance of the goods and/ or services performed. The terms of payment shall be within thirty (30) days, after receipt of invoice, and certification of acceptance of goods and/ or services issued by the proper authority in PAF: IAST. Payment will be affected by bank transfer in the currency of the contract. | | |
| | 47.2 The Contractor shall provide all necessary supporting documents along with GST invoice, delivery challan and any other relevant documents as required by the PAF-IAST. | | |

Section 3. Bid Data Sheet

The following data for the goods and/ or services to be procured shall complement, supplement, or amend the provisions in the Invitation to Bid. In the case of a conflict between the Instructions to Bidders, the Bid Data Sheet, and other annexes or references attached to the Bid Data Sheet, the provisions in the Bid Data Sheet shall prevail.

| BDS No. | Ref. to Section.2 | Data | Specific Instructions / Requirements |
|------------|----------------------|---------------------------|---|
| 1. | | Background of the Project | Pak-Austria Fachhochschule: Institute of Applied Sciences and Technology (PAF: IAST) is novel in its content and holistic in approach. The project concept is based on the slogan of "Skilling Pakistan" to create a high-quality technical education infrastructure. This unique educational institution in Pakistan will closely collaborate with several institutions in Austria and China and award multiple foreign degrees. This is a historic and visionary initiative as it is probably the first time that an institution will be established in Pakistan with many foreign universities giving degrees to students who study in it. |
| 2. | | Objective | The main objective of this Tender is to equip the PAF-IAST with necessary and advanced level of laboratory facilities, providing enabling environment to the students and faculty to perform their academic and research work in a conducive and productive environment and deliver beyond the expectations. |
| | | | Supply of Laboratory Equipment The required items in various Lots as referred in Section – 5 have been sought by Sino-Pak Center for Artificial Intelligence (SPCAI) from a reputed Firms/ Companies. The supplier is expected to supply high quality products meeting the specification as stipulated in this ITB, which conforms to the international quality standards. The time specified for delivery, Installation and Commissioning in the tender form shall be deemed to be the essence of the contract and the Successful Bidder shall arrange within the specified period. |
| 3. | | Scope of Work | Post-Delivery Warranty and Support Services It is required that Manufacturer's Warranty and Post-delivery Bidder's Support Services for at least One (01) year from the date of commissioning at PAF-IAST be provided by the Supplier within the quoted cost of items. |
| | | | |
| 4. | 7 | Language of the Bid | English |

| 5. | 22, 23, 27 | Submitting Bids for Parts or subparts of the Schedule of Requirements (partial bids) | The Purchase Committee shall consider the Bids Lot-wise (i.e. package against each of the Lots) as referred in Section – 5. Any item not quoted in the respective Lot shall have reasonable grounds to reject the Bid for that Lot. |
|-----|-------------------|---|--|
| 6. | 20 | Alternative Bids | Not Allowed. |
| 7. | 16 | Bid Validity Period | 90 days |
| 8. | 13 | Bid Security/ Earnest Money (Refundable) | Required in the amount of: 2% of the Bid Value amount (including Extended Warranty) quoted in DDP (in PKR) for each Lot (separately) against which the Bidder is participating. In case of options, earnest money shall be based on the maximum quoted price of the same items in the Lot. Acceptable Forms of Bid Security: Denominated in Pak Rupees duly issued by a Pakistani Bank or branch of a Foreign Bank, in the form of CDR in favor of the Project Director SPCAI, PAF-IAST |
| 9. | 42 | Liquidated Damages | Will be imposed as follows: Percentage of contract price per day of delay: as referred to in Draft Contract Sample in Annexure – II. |
| 10. | 40 | Performance Security | Within one week of issuance of LoI/ Purchase Order and well prior to the signing of Contract, as 10% of the Contract value for the duration of Warranty period referred in RFP. |
| 11. | 12 | Currency of Bid | Both Pakistani Rupees (PKR) for DDP |
| 12. | 31 | Deadline for submitting requests for clarifications/ questions | 5 days before the submission deadline |
| 13. | 31 | Contact Details for submitting clarifications/ questions | Focal Person in SPCAI: Dr. Sohail Khan sohail.khan@spcai.paf-iast.edu.pk Equipment related queries: Mr. Muhammad Usama Qureshi usama.qureshi@spcai.paf-iast.edu.pk Bid preparation and documentation related queries: Mr. Syed Wajid Shah wajid.shah@spcai.paf-iast.edu.pk |
| 14. | 18, 19, and 21 | Manner of Disseminating Supplemental Information to the ITB and responses/ clarifications to queries | Direct communication to prospective Bidders by email and/ or Posting on the PAF: IAST website: wajid.shah@spcai.paf-iast.edu.pk |
| 15. | 23 | Deadline for Submission | Tuesday the January 09, 2024 @ 12:00 noon (PST) |

| 16. | 22 | Number of Set(s) of Bid | - One (i - Soft c email <u>iast.ee</u> Financial Propo - One (i | 01) Original 01) Copy opy of Technica to Mr. Wajid Sh du.pk) osal(s) 01) Original are required to t(s) separately if | nah (<u>wajid.shah(</u> prepare and su | JSB Flash Drive or by @spcai.paf- bmit the Proposal(s) elopes, in which they |
|-----|-----------|--|--|--|--|--|
| 17. | 22 | Allowable Manner of Submitting Bids | ⊠ Courier/ Ha | nd Delivery | | |
| 18. | 22 | Bid Submission Address | | / Hand Delivery curement Comm ng, Haripur | | |
| 19. | 22 | Electronic submission (email) requirements | Not Allowed | | | |
| 20. | 25 | Date, time and venue for the opening of bid | | - | 024 @ 12:00 noo F-IAST, Mang, F | |
| 21. | 27, 36 | Evaluation Method | | | eting the PAF-IA Ilated in this ITB | AST requirements and |
| 22. | | Evaluation Method for the Award of Contract | Lowest priced | technically resp | oonsive | |
| 23. | | Expected date for commencement of Contract | February 2024 | ı | | |
| 24. | | Maximum expected duration of Contract | 36 months | | | |
| 25. | 35 | PAF: IAST will award the contract to: | One Bidder Or | nly against each | Lot | |
| 26. | 39 | Type and Contract Terms and Conditions that will apply | | eral Terms and (es as per Sampl | | ontracts for Goods |
| 27. | 46 | Delivery, Installation and Testing/ Training | LOT # 1-9 | Delivery 14-16 weeks | Installation 2 weeks | Testing/ Training 2 week |

Section 4. Evaluation Criteria

Preliminary Examination Criteria

Bids will be examined to determine whether they are complete and submitted in accordance with ITB requirements as per below criteria on a Yes/ No basis:

- · Appropriate signatures
- · Power of Attorney
- Minimum Bid documents provided.
- Bid Validity
- Bid Security submitted as per ITB requirements with compliant validity period

Minimum Eligibility Criteria

Eligibility will be evaluated on a Pass/ Fail basis. If the Bid is submitted as a Joint Venture, there should be no more than two (02) companies in the Joint Venture and each company should meet the minimum criteria, unless otherwise specified.

| | ELIGIBILITY | | |
|---------|------------------------------|---|---|
| S. # | Subject | Criteria | Reference Returnable Form(s) |
| 1. | Bidder's Status | Participating as ☐ Individual Company ☐ JV/ Consortium | Form B: Joint Venture/ Consortium/ Association Information Form |
| 2. | Legal Status | Bidder is a legally registered entity in Pakistan. Bidder is/ are also registered with FBR for Income Tax and Sales Tax | Form C: Bidder Information Form |
| 3. | Location of Offices | Bidder (Lead Bidder) has either declared office(s) in Islamabad/ Rawalpindi/ Peshawar or in Haripur. Alternately, if the Contract is awarded, the Bidder may be asked to establish office in either of these cities. | Form C: Bidder Information Form |
| 4. | Principal's Authorization | Bidder or at least one member of JV/ Consortium/ Association must be Authorized Partner/ Reseller/ Dealer for the supply and services of quoted goods/ services. | Form C: Bidder Information Form |
| 5. | Company in Operation | Bidder (Lead Bidder) is in operation for at least Five (05) years. | Form C: Bidder Information Form |
| 6. | Financial Strength | Average annual turnover over last 2 years no less than Rs. 3 million (For JV/ Consortium/ Association, all Parties cumulatively should meet requirement). | Form C: Bidder Information Form |
| 7. | Relevant Experience | Minimum No. of Projects of similar nature, value, and complexity in last 3 years Two (02) projects (For JV/Consortium/Association, all Parties cumulatively should meet requirement). | Form C: Bidder Information Form |

| 8. | Eligibility | Bidder(s) is not suspended, nor debarred, nor otherwise identified as ineligible by any Government/ Semi-government/ Autonomous organization in Pakistan, in accordance with ITB clause 3. | Form A: Bid Submission Form |
|----|-------------|---|--------------------------------|
| 9. | Bankruptcy | Bidder(s) has not declared bankruptcy, is not involved in bankruptcy or receivership proceedings, and there is no judgment or pending legal action against the vendor that could impair its operations in the foreseeable future. | Form A: Bid Submission Form |

| | QUALIFICATION | | | | |
|---------|-------------------------------------|--|---------------|--|---------------------------------------|
| S. # | Attribute | Description | Max. Score | Criteria | Returnable Form(s) |
| | Section – I: General Cor | porate Profile | 25 | | |
| 1. | Bidder's Footprints | Number of offices/ services centers across | 5 | 3+ offices fully operational for last five (05) year | Form C: Bidder Information |
| | | the country | 3 | 2 – 4 offices fully operational for last five (05) year | Form |
| | | | 1 | 1 offices fully operational for last two (02) year | |
| 2. | Bidder's Human Resource Strength | Number of full-time employees (documentary proof | 8 | 40+ employees with at least 20% Technical staff with at least 10% having technical certification | Form C: Bidder Information Form |
| | | required) | 6 | 25 – 39 employees with at least 20% Technical staff at least 10% having technical certification | |
| | | | 4 | 9 – 24 employees with at least 20% Technical staff at least 10% having technical certification | |
| | | | 2 | <8 employees with at least 20% Technical staff at least 10% having technical certification | |
| 3. | Financial Standing | Annual Turnover | 7 | 2+ x Financial Strength | Form D: |
| | | averaged over last 3 | 4 | 2 x Financial Strength | Qualification Form |
| | | years | 2 | 1.5 x Financial Strength | FOIIII |
| 4. | Annual Tax Paid | Annual Tax Paid | 5 | Rs. 2+ million or more | Form D: |
| | | averaged over last 3 | 3 | Rs. 1.0 – 2.0 million | Qualification Form |
| | | years | 2 | Rs. 0.5 – 1.0 million | 1 01111 |
| | Section – II: Business Pr | ofile | 30 | | |
| 5. | Relevant Experience | | 7 | Min. No. of Projects + 5 | |
| | | | 5 | Min. No. of Projects + 3 | |

| | | Project(s) of similar nature, value and complexity completed. | 3 | Min. No. of Projects + 2 | Form D: Qualification Form |
|-----|---|---|-------------------|--|---|
| 6. | Public Sector Experience | Project(s) delivered to government | 9 | 5 Projects worth \$0.5 million or more each | Form D: Qualification |
| | | organizations | 7 | 3 Projects worth \$0.25-0.49 million each | Form |
| | | | 5 | 2 Projects worth \$0.05-0.24 million each | |
| 7. | Education Sector | Project(s) completed at | 9 | 2+ Projects | Form D: |
| | Experience | education institutions. | 7 | 2 Projects | Qualification Form |
| | | | 5 | 1 Project | |
| 8. | Experience in KP | Project(s) completed in | 5 | Project worth Rs 5 million in KP | Form D: |
| | | КР | 3 | Project worth Rs 2.5 million in KP | Qualification Form |
| | Section – III: Manufactu Strengths | rer's/ Product's | 10 | | |
| 9. | Manufacturer's Global Presence | Countries having supplied the same Quoted items | 5 | No. of countries identified by Bid in consideration/ Max. No. of countries identified in all Bids * 10 | Form E: Project Proposal Form |
| 10. | Manufacturer's Products Portfolio | Various Products produced by the manufacturer beyond quoted items | 5 | No. of relevant Products mentioned by Bid in consideration/ Max. No. of Products referred in all | Form E: Project Proposal Form |
| | | quoteu items | | Bids * 10 | |
| | Section – IV: Registration | • | 10 | Bids * 10 | |
| 11. | Section – IV: Registration ISO 9001 Certified or equal if apply | • | 10 5 | Copy of Valid Certificate | Form E: Project Proposal Form |
| 11. | ISO 9001 Certified or | on & Certifications Bidder or the Lead Bidder in case of JV | | | - |
| | ISO 9001 Certified or equal if apply Certification specific to quoted Products/ | Bidder or the Lead Bidder in case of JV should be Certified Bidder or any of the JV Partners or Principal should possess them | 5 | Copy of Valid Certificate Copy of Valid Certificate(s) of the | Proposal Form Form E: Project |
| | ISO 9001 Certified or equal if apply Certification specific to quoted Products/ Solution | Bidder or the Lead Bidder in case of JV should be Certified Bidder or any of the JV Partners or Principal should possess them | 5 | Copy of Valid Certificate Copy of Valid Certificate(s) of the | Proposal Form Form E: Project |
| 12. | ISO 9001 Certified or equal if apply Certification specific to quoted Products/ Solution Section – V: Presentation | Bidder or the Lead Bidder in case of JV should be Certified Bidder or any of the JV Partners or Principal should possess them on on Project Proposal Overall approach towards planning and implementing the | 5 5 25 | Copy of Valid Certificate Copy of Valid Certificate(s) of the quoted Product(s) To be assigned by the Technical | Proposal Form Form E: Project Proposal Form Form E: Project |
| 12. | ISO 9001 Certified or equal if apply Certification specific to quoted Products/ Solution Section – V: Presentation Project Management Approach | Bidder or the Lead Bidder in case of JV should be Certified Bidder or any of the JV Partners or Principal should possess them on on Project Proposal Overall approach towards planning and implementing the project. Overall approach towards after-sale | 5 5 25 8 | Copy of Valid Certificate Copy of Valid Certificate(s) of the quoted Product(s) To be assigned by the Technical Committee To be assigned by the Technical | Form E: Project Proposal Form Form E: Project Proposal Form Form E: Project |

| Technical Evaluation | Bids shall be evaluated on both Eligibility and Technical Qualification Criteria. Bidders meeting the Eligibility Criteria and able to secure 60 percent in Technical qualification shall be declared as Technically Qualified Bidders for the next step, i.e. Opening of Financial Bid. |
|----------------------|---|
| Financial Evaluation | Detailed analysis of the price schedule based on requirements listed in Section 5 and quoted for by the bidders in Form F. Price comparison shall be based on the landed price, including transportation, insurance, duties, taxes and the total cost of ownership (including spare parts, consumption, installation, commissioning, training, special packaging, etc., where applicable). Comparison with budget/internal estimates. Tender will be awarded on least-cost basis . |

Section 5a: Technical Specifications of the Required Goods

| Custom-Build Agile Mult | icopter |
|---|--|
| Quantity: 1 | Code on the control to code of the code |
| Base | Carbon fiber multi-copter frame |
| Autopilot system | Pixhawk Autopilot |
| GPS | GPS CAN Module GPS / Module with CAN Bus |
| Camera | 4K Camera with gimbal |
| Propellers | Carbon fiber propellers with appropriate dimensions |
| Speed Controller | Electronic Speed Controller |
| Propeller motor | Brushless DC motors for propellers |
| Stand | Tripod Stand for Ground unit |
| RF Transceiver | RF Transmitter with Receiver |
| Cables | Servo Cable RF cables 12awg 14awg 16awg 20awg 26awg Silicon wires As per the mentioned technical specifications of multi-copte |
| Connectors | RF Connectors |
| Charger | Charger to meet the mentioned technical specifications of m copter |
| Telemetry | Telemetry Module with Telemetry Cables required for ensur communication with the Multicopter during flight radius |
| Battery 1 | Battery to meet the operational requirements for aerial unit |
| Battery 2 | Battery for ground unit. |
| Maximum Service Ceiling Above Sea Level: | 1000 m or better |
| Maximum Speed: | 30 Km/h or better |
| Maximum Flight Time: | 15 minutes or better |
| Maximum Flight radius: | 2 KM or better |
| Absolute accuracy | Vertical: ± 0.5m or better (with ground control points) Horizontal: ± 0.5m or better (with ground control points) |
| Software | Remote controller software that can be installed on the tabl navigation control and monitoring |
| On Multi-copter Video Recording: | 4K UHD or better |
| Video Live Stream | HD Video or better |

| | Addon 1 | Provision of on-board computer in terms of dimensions and compatibility with Jetson AGX Orin Developer Kits |
|---|---------------------------------------|--|
| | Addon 2 | Depth Camera |
| | Addon 3 | Camera Interface dev kit compatible with Jetson AGX Orin |
| | Addon 4 | Provision of on-board computer in terms of dimensions and compatibility with Raspberry pi 4 board (8GB+) |
| | Addon 5 | MB1220 XL-MaxSonar-EZ2 Rangefinders on each wing or equivalent or better for obstacle avoidance and are operational by default |
| 2 | PTV GNSS Base station (H | ere+V2 or Equivalent/Better) |
| _ | Quantity: 1 | ere+v2 or Equivalent/ better) |
| | GNSS module | u-blox NEO-M8P-2 or better |
| | Ceramic antenna | CGGBP.25.4.A.02 or better |
| | Connectors | At least the following connectors: USB, UART, SMA |
| | GNSS Signals Support | At least the following: GPS L1 C/A, GLONASS L10F, BeiDou B11 |
| | Working Voltage: | 5V or better |
| | Working Temperature: | -40°C to +85°C or better |
| | Time-To-First-Fix: | GPS & GLONASS: <=26s (cold start) or better <=1s (hot start) or better |
| | | <=2s (aided start) or better |
| 3 | Extra Aerial & Ground bat Quantity: 1 | teries |
| | Aerial Battery for Agile multi-copter | As per the technical specification of Agile multi-copter |
| | Ground Battery for Agile multi-copter | As per the technical specification of Agile multi-copter |
| | • | As per the technical specification of Carrier multi-copter |
| | | As per the technical specification of Carrier multi-copter |
| | | |

S. No. Lot 2: Customized Multi-copters Carrier Drone

| Custom-Built Carrier Multi-copter | | | | |
|---|---|--|--|--|
| Quantity: 1 | | | | |
| Base | Carbon fiber multi-copter frame | | | |
| Autopilot system | Pixhawk Autopilot | | | |
| GPS | GPS CAN Module GPS / Module with CAN Bus | | | |
| Camera | 4K Camera with gimbal or better | | | |
| Propellers | Carbon fiber propellers with appropriate dimensions | | | |
| Speed Controller | Electronic Speed Controller | | | |
| Propeller motor | Brushless DC motors for propellers | | | |
| Stand | Tripod Stand for Ground unit | | | |
| RF Transceiver | RF Transmitter with Receiver compatible with multi-copter | | | |
| Cables | Servo Cable RF cables 12awg 14awg 16awg 20awg 26awg Silicon wires As per the mentioned technical specifications of multi-copter | | | |
| Connectors | RF Connectors | | | |
| Charger | Charger to meet the mentioned technical specifications of multi- copter | | | |
| Telemetry | Telemetry Module with Telemetry Cables required for ensuring communication with the Multicopter during flight radius | | | |
| Battery 1 | Battery to meet the operational requirements for aerial unit | | | |
| Battery 2 | Battery for ground unit. | | | |
| Maximum Service Ceiling Above Sea Level: | 500 m or better | | | |
| Maximum Speed: | 20 Km/h or better | | | |
| Maximum Flight Time: | 30 minutes or better | | | |
| Maximum Flight radius: | 2 KM or better | | | |
| Load carrying capability | 5 KG or above | | | |
| Absolute accuracy | Vertical: ± 0.5m or better (with ground control points) Horizontal: ± 0.5m or better (with ground control points) | | | |
| Software | Remote controller software that can be installed on the tablet for navigation control and monitoring | | | |
| On Multi-copter Video Recording: | 4K UHD or better | | | |
| Video Live Stream | HD Video or better | | | |
| Video Interface | TCP/IP Ethernet | | | |

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| Lot 3: Drone Swarm and Safety Net | | | | |
|--|--|--|--|--|
| Flame-Retardant Drone Safety Net (Custom-Made) | | | | |
| Dimensions: 30 x 10 | 0 Feet | | | |
| Quantity: 1 | | | | |
| Material | high tenacity polypropylene, knotless, flame-retardant, or better | | | |
| Mesh Size | 45 x 45 mm or smaller | | | |
| Net Size | At least 30 x 100 Feet (width x length) | | | |
| Pose of Meshes | Quadratic (square) | | | |
| Mesh Connection | Knotless braid | | | |
| Edge Design | Reinforced selvage cord of approx. 7 mm or better | | | |
| Max. Tensile Strength Mesh | of a 700 N or better | | | |
| Standards and Rules | DIN 4102 (B1, flame-retarding), non-flaming dripping | | | |
| Certificate | MPA-Bau certification report P-NDS04-851, Oeko-Tex® certificate 12.0.02466 or equivalent | | | |
| Continuous Operating Temperature | g -40 to +80 °C or better | | | |
| Melting Point | 165 °C or better | | | |
| Tensile Strength After Years of Climatic Influences: | Two 90% or better | | | |
| Weight per Unit Area | <= 100 g/m² | | | |
| Flame-Retardant Dro Dimensions: 25 x 25 Quantity: 1 | one Safety Net (Custom-Made) Feet | | | |
| Material | high tenacity polypropylene, knotless, flame-retardant, o better | | | |
| Mesh Size | 45 x 45 mm or smaller | | | |
| Net Size | At least 30 x 70 Feet (width x length) | | | |
| Pose of Meshes | Quadratic (square) | | | |
| Mesh Connection | Knotless braid | | | |
| Edge Design | Reinforced selvage cord of approx. 7 mm or better | | | |
| Max. Tensile Strength Mesh | of a 700 N or better | | | |
| Standards and Rules | DIN 4102 (B1, flame-retarding), non-flaming dripping | | | |
| Certificate | MPA-Bau certification report P-NDS04-851, Oeko-Tex® certificate 12.0.02466 or equivalent | | | |
| Continuous Operating | | | | |
| T | 165 °C or better | | | |
| Temperature Melting Point | | | | |
| Melting Point Tensile Strength After Years of Climatic | | | | |
| Melting Point Tensile Strength After | Two 90% or better | | | |

The bundle contains the LPS system configuration which supports TDoA where a virtually infinite amount of Crazyflies can be positioned simultaneously. It also contains 10 Crazyflies with the LPS decks for positioning.

| Bundle content | |
|---|----------|
| Name | Quantity |
| Loco Positioning Nodes | 08 |
| Loco Positioning Deck | 10 |
| Crazyflie 2.1 kit | 10 |
| Crazyradio PA | 3 |
| 350mAh LiPo battery | 20 |
| including 500mA USB charger | 10 |
| Male spare connectors | 10 |
| Qi 1.2 wireless charging deck | 10 |
| Compatible WPC V1.2 based Qi charger | 10 |
| Spare part bundle: | 10 |
| 2 x Crazyflie 2.X spare motor (7mm DC motors) | |
| 2 x Crazyflie 2.X spare motor mounts pack (total of 8 motor mounts) | |
| 1 x Crazyflie 2.X spare propeller pack (4 x CW and 4 x CCW) | |
| Accessory – LED-ring deck | 10 |

Drone DJI Mavic 3 Pro or equivalent Quantity: 1 Weight Mavic 3 Pro: <1000 g Hasselblad Camera: 4/3 CMOS, Effective Pixels: 20 MP Camera: Medium Tele Camera: 1/1.3" CMOS, Effective Pixels: 48 Tele Camera: 1/2" CMOS, Effective Pixels: 12 MP Flight Time Greater than 40 minutes maximum Max Flight Distance greater than 25 km Video Transmission Protocol: O3+ or equivalent or better Range: 15km or better Rate:1080p/60fps Transmission* or better Drone position Omnidirectional binocular vision system 8 GB or better Internal storage Hybrid zoom tele camera 28x Zoom

| Hamana and an extensive to the | ialas [Camuras DMD] ita 220 au anuit al cata |
|---|--|
| Unmanned ground veh Quantity: 1 | icle: [Segway RMPLite 220 or equivalent] |
| Dimensions | L*W*H (mm): 730*499*280 |
| Structure | Axil base*Wheelbase*Ground |
| Parameters | clearance (mm): 513.5*413*69 |
| Tire size | 11 inches (280mm) Hub motor |
| Weight | 33KG |
| Standard Load | 50kg |
| Obstacle Avoidance | 5cm/8°/Speed bump |
| Suspension Travel | 4mm (Rear) |
| Drive | FWD, Differential Steering |
| IP Rating | IP65 |
| Max Speed | 3m/s |
| Max Steering Speed | 3rad/s |
| Minimum Turning Radius | Om |
| Braking | With No Load: 3m/s 0.9m, Braking Acc: 0.5g |
| Control | Remote control, host computer control |
| Braking Method | Electronic Brake |
| Interface | |
| | UART, CAN |
| Supporting system, API Feedback Data | C/C++, ROS |
| | Encoder, Hall, IMU |
| 3D Model | Gazebo, Rviz model |
| Battery | Range: 1152wh- Max Load:3m/s, Range:80Km |
| | Capacity: 48V 20Ah/24Ah |
| | Charging: Manual charging/Swappable battery/ Provided with |
| | automatic charging interface |
| B | Host computer power: 48V 400W |
| Buttons | Emergency stop button |
| | Push to move button |
| C | Power button |
| Status Indication | Power on/off status indicator |
| | Platform base status indicator |
| | Controls indication |
| | Battery level indicator |
| | Charging status indicator |
| Extension Kits | Must have provision for adding following |
| | Light Strip |
| | Infrared Sensor |
| | Ultrasonic Sensor |
| | Bumper Sensor |
| | Mounting Rod |
| Modern Manipulator Arn Quantity: 1 | n QArm – Quanser or Equivalent |
| Manipulator weight | 8.25 kg |
| Payload | 350 - 750 g |
| Reach | 750 mm |
| Repeatability | ± 0.05 mm |
| Camera | Camera Intel® RealSense™ D415 |
| Interface | USB (QFLEX 2) |
| Control | Internal control modes Position mode, Current mode |
| Control | External control rate 500 Hz |
| | Internal control rate (min) 1000 Hz |
| | |

| Maximum joint speed | ± 90o/s |
|---------------------|------------------|
| Minimum and maximum | Base: ± 1700 |
| joint range | Shoulder: ± 85 |
| | Elbow: -95o/+75o |
| | Wrist: ± 160o |
| | |
| | |
| | |

| S. No. | Lot 5: IoT, Sensors and IT Equ | lipment |
|--------|--------------------------------|--|
| L | Arduino Edge Control Qty: 10 | |
| | Microcontroller | nRF52840 (64 MHz Arm® Cortex-M4F) |
| | Digital Input | 6x edge sensitive wake up pins |
| | Digital Output | 8x latching relay command outputs with drivers |
| | | 8x latching relay command outputs without drivers |
| | Relays | 4x 60V/2.5A galvanically isolated solid-state relays |
| | Analog Input | 4x 4-20mA inputs |
| | | 8x 0-5V analog inputs |
| | | 16x hydrostatic watermark sensor input |
| | Terminal Block Connectors | 6x 18 pin plug in terminal block connectors |
| | Power Supply | 12 V Acid/lead SLA Battery Supply |
| | | (Recharged via solar panels) |
| | Power Consumption | Low power (up to 34 months on a 12V/5Ah battery) |
| | Mamary | 200uA Sleep current 1 MB onboard Flash memory |
| | Memory | 2 MB onboard QSPI Flash memory |
| | Sd Card | Interface for SD Card connector (through expansion port only) |
| | Connectivity | Bluetooth |
| | Connectivity | Wifi* |
| | | 3G*NB-IoT* |
| | | LoRaWAN®* |
| | | * Requires Arduino MKR board |
| | Peripherals | Full-speed 12 Mbps USB |
| | · | Arm CryptoCell CC310 security subsystem |
| | | QSPI/SPI/TWI/I ² S/PDM/QDEC |
| | | High speed 32 MHz SPI |
| | | Quad SPI interface 32 MHz |
| | | 12-bit 200 ksps ADC |
| | | 128 bit AES/ECB/CCM/AAR co-processor |
| | Operational Temperature | -40° C to +85° C (-40° F to 185°F) |
| 2 | Arduino Explore IoT Kit | |
| | Qty: 10 | |
| | Official Arduino Explore Kit | |
| | Must come with official box | ine platform with all the content, information, and activities to |
| | learn the basics of IoT in one | · · · · · · · · · · · · · · · · · · · |
| | | hands-on activities, covering the fundamentals of IoT: |
| | | ithms and programming, Security, Data handling |
| | | no Cloud, an integrated online platform that enables to write code |
| | | irds, and share projects. A free trial to the Arduino Cloud Maker |
| | Plan. with access to additiona | |
| | 1 x Arduino MKR1010 | |
| | MKR IoT Carrier designed for | this kit, including: |
| | 1. Two 24 V relays | |
| | 2. SD card holder | |
| | 3. Five Tactile buttons | |
| | 4. Plug and play connectors fo | or different sensors |
| | 5. Temperature sensor | |
| | 6. Humidity sensor | |
| | 7. Pressure sensor | |
| | 8. UV sensor | |

| 9. Accelerometer 10. RGB 1.20" display | |
|---|---|
| 11. 18650 Li-lon rechargeable l | pattery holder |
| 12. Five RGB LEDs | |
| 1 x Micro USB cable | |
| 1 x Moisture sensor | |
| 1 x PIR sensor | |
| Plug-and-play cables for all the | sensors |
| EMoRo 2560 Controller | |
| Qty: 10 Microcontroller | ATmega2560 |
| | 5 V |
| Operating Voltage | |
| Input Voltage (Recommended) | |
| Input Voltage (Limit) | 6-18 V |
| Digital I/O Pins | 40 => (16 with LEDs + 8 ADC + 8 Servo motor (PWM) + 8 Ger Purpose) |
| PWM Digital I/O Pins | 6 |
| Flash Memory | 256 KB (ATmega2560) |
| Flash Memory for Bootloader | 8 KB |
| SRAM | 8 KB (ATmega2560) |
| EEPROM | 4 KB (ATmega2560) |
| Clock Speed | 16 MHz |
| Analog Input Ports (ADC) | 8 |
| ARDUINO UNO WiFi REV2 | |
| Qty: 10 | |
| Microcontroller | ATmega4809 |
| Operating Voltage | 5V |
| Input Voltage (Recommended) | 7 - 12V |
| Digital I/O Pins | 14 — 5 Provide PWM Output |
| PWM Digital I/O Pins | 5 |
| Analog Input Pins | 6 |
| DC Current Per I/O Pin | 20 mA |
| DC Current For 3.3v Pin | 50 mA |
| Flash Memory | 48 KB (ATmega4809) |
| SRAM | 6,144 Bytes (ATmega4809) |
| EEPROM | 256 Bytes (ATmega4809) |
| Clock Speed | 16 MHz |
| <u> </u> | u-blox NINA-W102 (datasheet) |
| Radio Module | · · · · · · · · · · · · · · · · · · · |
| Radio Module Secure Element | ATECC608A (datasheet) |
| Secure Element | ATECC608A (datasheet) LSM6DS3TR (datasheet) |
| Secure Element Inertial Measurement Unit | LSM6DS3TR (datasheet) |
| Secure Element Inertial Measurement Unit Led_Builtin | |
| Secure Element Inertial Measurement Unit | LSM6DS3TR (datasheet) |
| Secure Element Inertial Measurement Unit Led_Builtin USB 2.0 Cable Type A/B Qty: 20 | LSM6DS3TR (datasheet) |

| 6 | Soldering Stand : QuadH | ands Classic Helping Hands Tool |
|----|--|---|
| | Qty: 2 | talius Classic Helping Hallus 1001 |
| | Soldering Stand | |
| | Four all-metal flexible goose | neck helping hands |
| | Heavy 8" by 8" powder coate | • • |
| | | ps can be rotated 360 degrees then "locked" into place with knurled |
| | thumb nuts. | po can be rotated 500 degrees then rotated into place with marred |
| 7 | | ic Pressure Sensor Grove(DPS310) or equivalent |
| | Qty: 10 | |
| | Based on DPS310 or equivale | hange caused by height changes in the centimeter level |
| 8 | | CO2 Sensor (0-50000ppm) |
| | Qty: 1 | , |
| | Operation Voltage | 4.5~5.5V |
| | Output | Gravity: UART |
| | Output | (0∼3.3V Level) |
| | Measurement Principle | NDIR (non-dispersive infrared) |
| | Measurement Range | 0∼50000 ppm |
| | Accuracy | ±(100ppm + 6% readings) |
| | Response Time | <30s |
| | Average Power | <430mW@5V |
| | Operation Temperature | 0°C~50°C |
| | Operation Humidity | 0∼95% RH (No condensation) |
| | Lifespan | >5 years |
| | Dimension (PCB) | 21*27.1 mm |
| | | 1.High Accuracy |
| | | 2.Large Range |
| | Features | 3.Long Lifespan |
| | | 4.Auto Temperature Compensation 5.Water Vapor Interference Resistance |
| | | 6.3.3V UART Output |
| 9 | Grove - Gas Sensor (MQ | · |
| | Qty: 10 | |
| | | ng Alcohol, Benzine, CH4, Hexane, LPG, CO. |
| 10 | | r can be adjusted by using the potentiometer. Sensor (MG-811 Sensor) |
| 10 | Qty: 10 | s Sensor (IVIO-811 Sensor) |
| | | sensor module (highly sensitive to CO2 and less sensitive to alcohol |
| | and CO, low humidity & tem | |
| | Operating Voltage:5V | |
| | Interface: Gravity Analog | |
| | One digital output | |
| | High-quality connector Immersion gold surface | |
| | Onboard heating circuit | |
| 11 | | ve Soil Moisture Sensor - Corrosion Resistant |
| | Must be made of corrosion r | resistant material |
| | Must have On-board voltage | |
| | Operating voltage range: 3.3 | |
| | Must be compatible with Mo | CUs (both 3.3V and 5V logic) |

| 40 | |
|----|---|
| 12 | Digital Infrared Temperature Sensor (Grove or equivalent) Qty: 10 |
| | Non-contact temperature measurement |
| | Based on MLX90615. |
| | Must contain IR sensitive thermopile detector chip and the signal conditioning chip in the same |
| | package. |
| | Communication with Arduino using SMBus |
| | Up to 127 sensors can be read via common 2 wires. |
| | 16-bit ADC |
| | Accuracy of 1°C over wide temperature rage and a high measurement resolution of 0.02°C. |
| | - 40 to 85°C for sensor temperature |
| 40 | - 40 to 115°C for object temperature |
| 13 | Multi-function Environmental Module - CCS811+BME280 |
| | Qty: 10 Multi-function environment sensor |
| | Based on the combination of CCS811+BME280 chip |
| | I2C interface |
| | Must be able to detect temperature, humidity, barometric pressure, altitude, TVOC, and eCO2. |
| | ±0.5°C temperature error |
| | ±2%RH humidity error |
| | Offset temperature coefficient: ±1.5 Pa/K, equiv. to ±12.6 cm at 1 °C temperature change. |
| 14 | Gravity: Non-contact Digital Water / Liquid Level Sensor For Arduino |
| | Qty: 20 |
| | Non-contact water / liquid level sensor for Arduino |
| | Chip: (XKC-Y25-T12V) |
| 15 | Air Quality Sensor (CCS811 DFRobot or equivalent) |
| | Qty: 20 |
| | Must be able to measure the eCO ₂ (equivalent CO ₂) and TVOC (Total Volatile Organic |
| | Compounds) density. |
| | Must use AMS's unique micro-hot plate technology or equivalent Must have Internally integrated ADCs and MCUs allow data to be collected, calculated, and |
| | returned via I2C. |
| | Must support a concentration alarm, which is triggered when the concentration exceeds the |
| | threshold. |
| | Must support multiple modes |
| | Must have sleep mode |
| 16 | Water Sensor (Grove or equivalent) |
| | Qty: 20 |
| | Grove compatible interface |
| | Low power consumption |
| | ~ 2.0cm x 2.0cm |
| | High sensitivity |
| | Working Voltage: 4.75-5.25 V |
| | Current <20mA |
| | Working Humidity (Without Condensation) 10-90 % |
| 17 | Must come with the interface wire pack Temperature Sensor (Grove or equivalent) |
| 17 | Qty: 20 |
| | Voltage: 3.3 ~ 5V |
| | Zero power resistance: 100 KΩ |
| | Resistance Tolerance: ±1%20 |
| | Operating temperature range: -40 ~ +125 °C |
| | Nominal B-Constant: 4250 ~ 4299K |
| | Must come with the interface wire pack |
| | |
| I | |

| I/O Voltage Operating Current Operating Temperature Atmospheric Pressure Sensor Measurement Range Temperature Sensor Measurement Range Humidity Sensor Measurements Range Measurement Modes Chip Interface Bus Weight Dimensions Parameter | 3.3V or 5V 3.3V or 5V 0.4mA -40 - 85 °C 300 - 1100 hPa (1 hPa= one hundred Pa) with ±1.0 hPa accurace -40 - 85 °C, with ±1.0°C accuracy 0% - 100% relative humidity , with ±3% accuracy Piezo & Temperature, forced or periodic BME280(datasheet) SPI, I2C (use either one of them) 3.2 g (for breakout board), 9.3 g for whole package each piece 40 (length) × 20 (width) mm |
|--|---|
| Operating Current Operating Temperature Atmospheric Pressure Sensor Measurement Range Temperature Sensor Measurement Range Humidity Sensor Measurements Range Measurement Modes Chip Interface Bus Weight Dimensions Parameter | 0.4mA -40 - 85 °C 300 - 1100 hPa (1 hPa= one hundred Pa) with ±1.0 hPa accurace -40 - 85 °C, with ±1.0°C accuracy 0% - 100% relative humidity, with ±3% accuracy Piezo & Temperature, forced or periodic BME280(datasheet) SPI, I2C (use either one of them) 3.2 g (for breakout board), 9.3 g for whole package each piece 40 (length) × 20 (width) mm |
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| Atmospheric Pressure Sensor Measurement Range Temperature Sensor Measurement Range Humidity Sensor Measurements Range Measurement Modes Chip Interface Bus Weight Dimensions Parameter | 300 - 1100 hPa (1 hPa= one hundred Pa) with ±1.0 hPa accuracy -40 - 85 °C, with ±1.0°C accuracy 0% - 100% relative humidity, with ±3% accuracy Piezo & Temperature, forced or periodic BME280(datasheet) SPI, I2C (use either one of them) 3.2 g (for breakout board), 9.3 g for whole package each piece 40 (length) × 20 (width) mm |
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| Measurement Range Humidity Sensor Measurements Range Measurement Modes Chip Interface Bus Weight Dimensions Parameter | 0% - 100% relative humidity , with ±3% accuracy Piezo & Temperature, forced or periodic BME280(datasheet) SPI, I2C (use either one of them) 3.2 g (for breakout board), 9.3 g for whole package each piece 40 (length) × 20 (width) mm |
| Measurements Range Measurement Modes Chip Interface Bus Weight Dimensions Parameter | Piezo & Temperature, forced or periodic BME280(datasheet) SPI, I2C (use either one of them) 3.2 g (for breakout board), 9.3 g for whole package each piece 40 (length) × 20 (width) mm |
| Chip Interface Bus Weight Dimensions Parameter | BME280(datasheet) SPI, I2C (use either one of them) 3.2 g (for breakout board), 9.3 g for whole package each piece 40 (length) × 20 (width) mm |
| Interface Bus Weight Dimensions Parameter | SPI, I2C (use either one of them) 3.2 g (for breakout board), 9.3 g for whole package each piece 40 (length) × 20 (width) mm |
| Weight Dimensions Parameter | 3.2 g (for breakout board), 9.3 g for whole package each piece 40 (length) \times 20 (width) mm |
| Dimensions Parameter | 40 (length) × 20 (width) mm |
| Parameter | |
| | |
| Input Voltage | Value |
| | 3.3V or 5V |
| I/O Voltage | 3.3V or 5V |
| Operating Current | 0.4mA |
| Operating Temperature | -40 - 85 °C |
| Atmospheric Pressure Sensor | 300 - 1100 hPa (1 hPa= one hundred Pa) with ±1.0 hPa accurac |
| Temperature Sensor Measurement Range | -40 - 85 °C, with ±1.0°C accuracy |
| Humidity Sensor Measurements Range | 0% - 100% relative humidity , with ±3% accuracy |
| Moisture Sensor (Grove or Qty: 20 | equivalent) |
| Dimensions | 60mm x20mm x6.35mm |
| Weight | G.W 10g |
| Battery | Exclude |
| Operating voltage | 3.3~5V |
| Operating current | 35mA |
| Sensor Output Value in dry soil | 0~ 300 |
| Sensor Output Value in humid soil | 300~700 |
| - | 700 ~ 950 |
| Hall Sensor (Grove or equiv Qty: 10 | valent) |
| 400ns transition period for rise | and fall. |
| Analog pH Sensor / Meter Qty: 10 | Pro Kit For Arduino (Gravity or equivalent) |
| Professional pH Sensor Meter K Life (up to 1 year) | (it with industrial electrode. |
| | Weight Battery Operating voltage Operating current Gensor Output Value in dry soil Gensor Output Value in humid soil Gensor Output Value in water Hall Sensor (Grove or equivalue) 1000ns transition period for rise Analog pH Sensor / Meter Oty: 10 Operofessional pH Sensor Meter Re |

Accuracy : ± 0.1pH (25 °C) Response Time : ≤ 1min

Industry pH Electrode with BNC Connector

PH2.0 Interface (3 foot patch)
Gain Adjustment Potentiometer

Power Indicator LED

Kit must contain the following:

Industry pH electrode (BNC connector) x1

pH sensor circuit board x1

Analog cable x1

Ozone Sensor (0-10ppm) (Gravity or equivalent)

Qty: 10

Detection Gas: Ozone

Working Voltage: 3.3 ~ 5.5V DC
Interface: Gravity-4Pin
Output Signal: I2C output
Measuring Range: 0 ~ 10ppm
Resolution: 0.01ppm (10ppb)
Warm-up Time: ≤3 minutes
Response Time: ≤90 seconds
Recovery Time: ≤90 seconds

Operating Humidity: 15 ~ 95% RH (non-condensing)

Storage Temperature: -20 ~ 50 °C

Working Temperature: -20 ~ 50 °C

Life:> 2 years (in air)

23 SOIL HUMIDITY SENSOR, WATERMARK 2 M / 75 CM (Pack of 6)

Qty: 10

Range 0 – 239 cbars,

Frost resistant

Watermark sensors must be glued/riveted on a semi-tender PVC tube that is re-molded back in 2 diameters 25/22 mm

24 Arduino Nano 33 IoT with headers

Qtv: 10

| Qty. 10 | |
|-----------------------------|---|
| Microcontroller | SAMD21 Cortex®-M0+ 32bit low power ARM MCU |
| Radio module | u-blox NINA-W102 |
| Secure element | ATECC608A |
| Operating voltage | 3.3V |
| Input voltage (limit) | 21V |
| DC Current Per I/O Pin | 7 mA |
| Clock Speed | 48MHz |
| CPU Flash Memory | 256KB |
| SRAM | 32KB |
| EEPROM | none |
| Digital Input / Output Pins | 14 |
| PWM PINS | 11 (2, 3, 5, 6, 9, 10, 11, 12, 16 / A2, 17 / A3, 19 / A5) |
| UART | 1 |
| SPI | 1 |
| 12C | 1 |
| Analog input pins | 8 (ADC 8/10/12 bit) |
| Analog output pins | 1 (DAC 10 bit) |
| External interrupts | All digital pins (all analog pins can also be used as interrput pins, |

| | | but will have duplicated interrupt numbers) | | |
|----|--|--|--|--|
| | Led Built-in | 13 | | |
| | USB | Native in the SAMD21 Processor | | |
| | IMU | LSM6DS3 | | |
| 25 | WiFi Module - ESP8 | | | |
| 23 | Qty: 20 | 2200 (HIVID Flash) | | |
| | 802.11 b/g/n | | | |
| | Wi-Fi Direct (P2P), soft | -AP | | |
| | Integrated TCP/IP prot | | | |
| | | palun, LNA, power amplifier and matching network | | |
| | | itors, DCXO and power management units | | |
| | +19.5dBm output pow | | | |
| | Power down leakage c | urrent of <10uA | | |
| | 4MB Flash Memory | 33 kit CDU | | |
| | Integrated low power: SDIO 1.1 / 2.0, SPI, UAI | | | |
| | STBC, 1×1 MIMO, 2×1 | | | |
| | | gregation & 0.4ms guard interval | | |
| | Wake up and transmit | | | |
| | - | nption of < 1.0mW (DTIM3) | | |
| | Soldered Headers | | | |
| 26 | ESP-01S Wifi Modu | le with relay or equivalent | | |
| | Qty: 20 | | | |
| | Supply Voltage: DC 5V | | | |
| | | A 250VAC ,10A 125VAC, 10A 30VDC, 10A 28VDC | | |
| 27 | | Module (Adafruit or equivalent) | | |
| | Qty: 10 Supply voltage: 3.6 - 6. | 0\/DC | | |
| | | | | |
| | Operating current: 120mA max Peak current: 150mA max | | | |
| | Fingerprint imaging time: <1.0 seconds | | | |
| | Window area: 14mm x 18mm | | | |
| | Signature file: 256 bytes | | | |
| | Template file: 512 bytes | | | |
| | Storage capacity: 162 templates | | | |
| | Safety ratings (1-5 low | | | |
| | - | : <0.001% (Security level 3) | | |
| | False Reject Rate: <1.0 Interface: TTL Serial | % (Security level 3) | | |
| | | 0, 28800, 38400, 57600 (default is 57600) | | |
| | Working temperature | • | | |
| | Working humidity: 409 | | | |
| 28 | | al Time Clock Assembled Breakout Board | | |
| | Qty: 10 | | | |
| | RTC: DS1307 | | | |
| | Breakout board with h | | | |
| | Battery cell must be in | | | |
| 29 | | TC Breakout (Adafruit or equivalent) | | |
| | Qty: 5 | | | |
| | RTC: DS3231 | aadaya | | |
| | Breakout board with h Battery cell must be in | | | |
| 30 | | couded cout board+(Adafruit or equivalent) | | |
| 30 | Qty: 10 | Controlled (Additate of Equivalent) | | |
| | * | | | |

| | b (F. L. Jakistina) | | | |
|------------|---|--|--|--|
| | 3v/5v level shifting | | | |
| | Activity LED lights up when the SD card is being read or written | | | |
| _ | Compatible with Arduino | | | |
| 31 | HDMI Cables for Raspberry Pi 4 B+ (Micro HDMI to HDMI) | | | |
| | Qty: 30 | | | |
| | HDMI A (Standard) to HDMI D (micro) | | | |
| | 19-pin HDMI Type D(M) to 19-pin HDMI Type A(M) | | | |
| | Nickel-plated plugs | | | |
| | 4Kp60 compliant | | | |
| | RoHS compliant | | | |
| | 3Mohm 300VDC insulation withstands 300VDC for 0.1s | | | |
| | Compliant with HDMI high-speed cable standards | | | |
| | Must support both audio and video | | | |
| | Must support Ethernet and Audio Return Channel (CEC) | | | |
| 32 | Hot Air Soldering Rework Station w/ Three Nozzles – Quick 957DW+ | | | |
| J 2 | Qty: 2 | | | |
| | Closed-loop temperature control range between 100-450°C | | | |
| | | | | |
| | Digital display | | | |
| | Intelligent cooling system so the airflow remains on until it gets to below 100°C. | | | |
| | Max air flow is 100L/minute | | | |
| | Technical Details | | | |
| | Rework Station: 180mm x 99mm x 145mm / 7.1" x 3.9" x 5.7" | | | |
| | Hose Length: 105 cm / 41.5" | | | |
| | Weight: 1588g / 3.5lbs | | | |
| | 120VAC – 580 Watts | | | |
| | Outer Diameters of Three Nozzles: | | | |
| | 3mm / 0.12" | | | |
| | 6.4mm / 0.25" | | | |
| | 8.4mm / 0.33" | | | |
| 33 | Engineer Professional Silicone-Tip Solder Sucker | | | |
| | Qty: 2 | | | |
| | Dimensions: 8.1 x 3.4 x 0.7 inches | | | |
| | Weight: 52g | | | |
| | | | | |
| 1 | | | | |
| 2.4 | Cylinder Capacity: 9cc | | | |
| 34 | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D | | | |
| 34 | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 | | | |
| 34 | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron | | | |
| 34 | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron Power Voltage: 110V AC / 60Hz | | | |
| 34 | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron Power Voltage: 110V AC / 60Hz Power Consumption: 80W | | | |
| 34 | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron Power Voltage: 110V AC / 60Hz | | | |
| | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron Power Voltage: 110V AC / 60Hz Power Consumption: 80W Temperature Range: 80 ~ 480°C / 176 ~ 896ºF | | | |
| 34 | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron Power Voltage: 110V AC / 60Hz Power Consumption: 80W | | | |
| | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron Power Voltage: 110V AC / 60Hz Power Consumption: 80W Temperature Range: 80 ~ 480°C / 176 ~ 896ºF | | | |
| | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron Power Voltage: 110V AC / 60Hz Power Consumption: 80W Temperature Range: 80 ~ 480°C / 176 ~ 896°F 128 GB Extreme microSDHC UHS-I Memory Card with Adapter or equivalent | | | |
| | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron Power Voltage: 110V AC / 60Hz Power Consumption: 80W Temperature Range: 80 ~ 480°C / 176 ~ 896°F 128 GB Extreme microSDHC UHS-I Memory Card with Adapter or equivalent Qty: 40 | | | |
| | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron Power Voltage: 110V AC / 60Hz Power Consumption: 80W Temperature Range: 80 ~ 480°C / 176 ~ 896ºF 128 GB Extreme microSDHC UHS-I Memory Card with Adapter or equivalent Qty: 40 Class: 10 Up to 160MB/s read speeds to save time transferring high-res images and 4K UHD videos | | | |
| | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron Power Voltage: 110V AC / 60Hz Power Consumption: 80W Temperature Range: 80 ~ 480°C / 176 ~ 896°F 128 GB Extreme microSDHC UHS-I Memory Card with Adapter or equivalent Qty: 40 Class: 10 Up to 160MB/s read speeds to save time transferring high-res images and 4K UHD videos Up to 60MB/s write speeds for fast shooting. | | | |
| | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron Power Voltage: 110V AC / 60Hz Power Consumption: 80W Temperature Range: 80 ~ 480°C / 176 ~ 896ºF 128 GB Extreme microSDHC UHS-I Memory Card with Adapter or equivalent Qty: 40 Class: 10 Up to 160MB/s read speeds to save time transferring high-res images and 4K UHD videos Up to 60MB/s write speeds for fast shooting. 4K UHD and Full HD-ready with UHS Speed Class 3 (U3) and Video Speed Class 30 (V30)(5) | | | |
| | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron Power Voltage: 110V AC / 60Hz Power Consumption: 80W Temperature Range: 80 ~ 480°C / 176 ~ 896ºF 128 GB Extreme microSDHC UHS-I Memory Card with Adapter or equivalent Qty: 40 Class: 10 Up to 160MB/s read speeds to save time transferring high-res images and 4K UHD videos Up to 60MB/s write speeds for fast shooting. 4K UHD and Full HD-ready with UHS Speed Class 3 (U3) and Video Speed Class 30 (V30)(5) Rated A2 for faster loading and in-app performance | | | |
| | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron Power Voltage: 110V AC / 60Hz Power Consumption: 80W Temperature Range: 80 ~ 480°C / 176 ~ 896°F 128 GB Extreme microSDHC UHS-I Memory Card with Adapter or equivalent Qty: 40 Class: 10 Up to 160MB/s read speeds to save time transferring high-res images and 4K UHD videos Up to 60MB/s write speeds for fast shooting. 4K UHD and Full HD-ready with UHS Speed Class 3 (U3) and Video Speed Class 30 (V30)(5) Rated A2 for faster loading and in-app performance Built for and tested in harsh conditions: temperature-proof, water-proof, shock-proof and x-ray | | | |
| 35 | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron Power Voltage: 110V AC / 60Hz Power Consumption: 80W Temperature Range: 80 ~ 480°C / 176 ~ 896ºF 128 GB Extreme microSDHC UHS-I Memory Card with Adapter or equivalent Qty: 40 Class: 10 Up to 160MB/s read speeds to save time transferring high-res images and 4K UHD videos Up to 60MB/s write speeds for fast shooting. 4K UHD and Full HD-ready with UHS Speed Class 3 (U3) and Video Speed Class 30 (V30)(5) Rated A2 for faster loading and in-app performance Built for and tested in harsh conditions: temperature-proof, water-proof, shock-proof and x-ray proof | | | |
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| 35 | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron Power Voltage: 110V AC / 60Hz Power Consumption: 80W Temperature Range: 80 ~ 480°C / 176 ~ 896°F 128 GB Extreme microSDHC UHS-I Memory Card with Adapter or equivalent Qty: 40 Class: 10 Up to 160MB/s read speeds to save time transferring high-res images and 4K UHD videos Up to 60MB/s write speeds for fast shooting. 4K UHD and Full HD-ready with UHS Speed Class 3 (U3) and Video Speed Class 30 (V30)(5) Rated A2 for faster loading and in-app performance Built for and tested in harsh conditions: temperature-proof, water-proof, shock-proof and x-ray proof Wire Stripper Qty: 2 | | | |
| 35 | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron Power Voltage: 110V AC / 60Hz Power Consumption: 80W Temperature Range: 80 ~ 480°C / 176 ~ 896ºF 128 GB Extreme microSDHC UHS-I Memory Card with Adapter or equivalent Qty: 40 Class: 10 Up to 160MB/s read speeds to save time transferring high-res images and 4K UHD videos Up to 60MB/s write speeds for fast shooting. 4K UHD and Full HD-ready with UHS Speed Class 3 (U3) and Video Speed Class 30 (V30)(5) Rated A2 for faster loading and in-app performance Built for and tested in harsh conditions: temperature-proof, water-proof, shock-proof and x-ray proof Wire Stripper | | | |
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| 35 | Cylinder Capacity: 9cc ATTEN 80W 110V Soldering Iron With Station - ST-2090D Qty: 6 80 Watt-powerful stationary soldering iron Power Voltage: 110V AC / 60Hz Power Consumption: 80W Temperature Range: 80 ~ 480°C / 176 ~ 896°F 128 GB Extreme microSDHC UHS-I Memory Card with Adapter or equivalent Qty: 40 Class: 10 Up to 160MB/s read speeds to save time transferring high-res images and 4K UHD videos Up to 60MB/s write speeds for fast shooting. 4K UHD and Full HD-ready with UHS Speed Class 3 (U3) and Video Speed Class 30 (V30)(5) Rated A2 for faster loading and in-app performance Built for and tested in harsh conditions: temperature-proof, water-proof, shock-proof and x-ray proof Wire Stripper Qty: 2 | | | |

| | Breadboard power supply |
|----|---|
| 37 | Qty: 10 |
| | 5V |
| | 3V |
| 38 | Vero board |
| | Qty: 20 |
| | Different standard sizes |
| | Breadboard size, 2x breadboard size |
| 39 | Magnifying glass for soldering |
| | Qty: 5 |
| | 3 kinds of magnifying lens: 2.5X 90mm (diameter), 7.5X 34mm, 10X 34mm. |
| | Independent bright illuminating light with 5 pcs of LEDs. |
| | Base surface: steel sheet. |
| | Lens diameter: 90mm & 34mm |
| | Power: external power or 3 * AA Battery (not included) |
| | Power adapter: Input 110-240V 50/60Hz, Output: DC 4.8V 250mA |
| | Welding holder size: length 6.3cm/2.48in, Diameter 2.7cm & 1.8cm/ 1.06in 0.71in |
| | Base size: 10 * 6.8cm / 3.94 * 2.68in (L * W) |
| 40 | Breadboard |
| | Qty: 20 |
| | 2 Distribution Strips, 200 tie-points |
| | 630 tie-points in IC/ circuit areas |
| | ABS plastic with color legend |
| | Dimension: 6.5*4.4*0.3 inch |
| | Hole/Pitch Style: Square wire holes (2.54mm) |
| | ABS heat Distortion Temperature: 84° C (183° F) |
| | Rating: 300/3 to 5Amps |
| | Insulation Resistance: 500MΩ / DC500V |
| | Withstanding Voltage: 1,000V AC / 1 minute Insertion Wire Size: 21 to 26 AWG wire |
| 41 | RAM - 16GB DDR4 3200MHz SODIMM PC4-25600 |
| 41 | Qty: 12 |
| | Speed: PC4-25600 (3200 MHz) |
| | Memory Type: DDR4 |
| 42 | SATA 2.5" SSD 512GB for laptops |
| 42 | Qty: 10 |
| | Contents: |
| | SATA III Solid State Drive |
| | Capacity:512GB |
| 43 | Keyboards |
| | Qty: 30 |
| | Logitech MK850 performance wireless Keyboard and Mouse set |
| | |

| Lot 6 | Embedded Systems | | |
|-------|---|--|--|
| 1 | WiFi LoRa 32 Dev Board (Heltec or equivalent) | | |
| | Qty: 10 | | |
| | Processor: Tensilica LX6 dual-core processor, clocked at 240MHz, computing power up to | | |
| | 600DMIPS, | | |
| | SRAM: chip built-in 520 KB SRAM | | |
| | Wi-Fi: ESP32 series 802.11b/g/n HT40 Wi-Fi transceiver, baseband, protocol stack and LWIP | | |
| | Integrated dual-mode Bluetooth (traditional Bluetooth and BLE low power Bluetooth). | | |
| | Lora: SX1276 chip, 868/915MHz frequency, -139dBm high sensitivity, | | |
| | +20 dBm power output, high reliability, transmission distance (measured open area | | |
| | communication distance 2.8Km). | | |
| | Onboard 32MByte Flash | | |
| | 0.96-inch blue OLED display | | |
| | Lithium battery charging circuit and interface | | |
| | CP2102 USB to serial chip | | |
| | Operating voltage: 3.3V to 7V | | |
| | Operating temperature range: -40 ° C to + 90 ° C | | |
| | Supports Sniffer, Station, softAP and Wi-Fi Direct modes | | |
| | Data rate: 150 Mbps 11n HT40,72 Mbps 11n HT20,54 Mbps 11g, 11 Mbps 11b | | |
| | Transmit power: 19.5 dBm 11b, 16.5 dBm 11g, 15.5 dBm 11n | | |
| | Receiver sensitivity up to - 139 dBm | | |
| | UDP continues to throughput by 135 Mbps | | |
| | Antenna Specifications: | | |
| | Connector type: ipex Band definition: 868-915MHz | | |
| | | | |
| | Standing wave ratio: ≦ 1.5 Gain: 3dBi | | |
| | Maximum power: 10W | | |
| | Input impedance: 50Ω | | |
| | Package must include | | |
| | 1 * ESP32 Development Board with OLED | | |
| | 1 * 868/915MHz Antenna | | |
| | 1 * Pin sticker | | |
| | 2 * Pin headers | | |
| 2 | LoRa Test Board Kit (LLCC68 based E220-900T30S or equivalent) | | |
| | Qty: 2 | | |
| | For testing the EBYTE E220-900T30S Lora Transceiver | | |
| | All pins of E220-900T30S module have been led out | | |
| | Pre-welded E220-900T30S | | |
| | Must be Equipped with USB interface, can be directly plugged into the computer to use | | |
| | Working Frequency: 850.125-930.125MHz | | |
| | IC: LLCC68 or equivalent | | |
| | Module Size: 80*45mm | | |
| | Operating Voltage: 3.3-5.5V | | |
| | Power: 30dBm | | |
| | Receiving Sensitivity: -129dBm | | |
| | Antenna must be included | | |
| 3 | LoRa LLCC68 Development Kit 430 MHz 470 MHz | | |
| | Qty: 2 | | |
| | For testing the EBYTE E220-400T30S Lora Transceiver | | |
| | All pins of E220-400T30S module have been led out | | |
| | Pre-welded E220-400T30S | | |
| | Must be Equipped with USB interface, can be directly plugged into the computer to use | | |
| | Working Frequency: 430Mhz-470Mhz | | |
| | IC: LLCC68 or equivalent | | |
| | Module Size: 80*45mm | | |

| | Operating Voltage: 3.3-5.5V |
|---|---|
| | Power: 30dBm |
| | Receiving Sensitivity: -129dBm |
| | Antenna must be included |
| | Must include USB power supply cable |
| 4 | LLCC68 LoRa Module 868MHz 915MHz 30dBm UART |
| | Qty: 10 |
| | Certification: CE, FCC, RoHS |
| | Working Frequency: 868MHz 915MHz |
| | Model Number: E220-900T30D |
| | IC: LLCC68 |
| | Working Frequency: 850.125~930.125MHz |
| | Power: 30dBm |
| | Distance: 10km |
| | Size: 24*43mm |
| | Communication Distance: UART |
| | |
| | Package Type: DIP |
| F | Antenna Type: SMA-K LLCC68 LoRa Module 433MHz 470MHz 30dBm UART |
| 5 | |
| | Qty: 10 |
| | Certification: CE, FCC, RoHS |
| | Origin: CN(Origin) |
| | Working Frequency: 433MHz |
| | Model Number: E220-400T30D |
| | IC: LLCC68 |
| | Working Frequency: 410.125~493.125MHz |
| | Power: 30dBm |
| | Distance: 10km |
| | Size: 24*43mm |
| | Antenna Type: SMA-K |
| | Communication Distance: UART |
| 6 | Antenna for LLCC68 LoRa Module 868MHz 915MHz 30dBm UART Qty: 10 |
| | · |
| 7 | Antenna compatible with item specs (S. No. 69) |
| / | DE1-SoC Development Kit including cables and power adapter |
| | Qty: 2 |
| | Detailed Specs: |
| | Cyclone V SoC FPGA 5CSEMA5F31 with EPCQ256 256-Mbit serial configuration device |
| | ARM* Cortex-A9 dual core (925 MHz) |
| | Nios® II processor |
| 8 | DE10-Lite |
| | Qty: 10 |
| | Intel® MAX® 10 FPGA 10M50DAF484C7G with integrated dual ADCs. Each ADC supports one |
| | dedicated analog input and eight dual function pins |
| | Nios II processor |
| 9 | Super Value Ultimate 37 in 1 Sensor Modules Kit for Arduino & MCU |
| | Qty: 08 |
| | 1 x Small passive buzzer module KY-006 – |
| | 1 x 2-color LED module KY-011 |
| | 1 x Hit sensor module KY-031 |
| | 1 x Vibration switch module KY-002 |
| | 1 x Photo resistor module KY-018 |
| | 1 x Key switch module KY-004 |
| | 1 x Tilt switch module KY-020 |
| | 1 x 3-color full-color LED SMD modules KY-009 |
| | |

| | 1 x Infrared emission sensor module KY-005 |
|----------|--|
| | 1 x 3-color LED module KY-016 |
| | 1 x Mercury open optical module KY-017 |
| | 1 x Yin Yi 2-color LED module 3MM KY-029 |
| | 1 x Active buzzer module KY-012 |
| | 1 x Temperature sensor module KY-013 |
| | 1 x Automatic flashing colorful LED module KY-034 |
| | 1 x Mini magnetic reed modules KY-021 |
| | 1 x Hall magnetic sensor module KY-003 |
| | 1 x Infrared sensor receiver module KY-022 |
| | 1 x Class Bihor magnetic sensor KY-035 |
| | 1 x Class Billot Hagnetic sensor K1-033 |
| | |
| | 1 x Rotary encoder module KY-040 |
| | 1 x Optical broken module KY-010 |
| | 1 x Detect the heartbeat module KY-039 |
| | 1 x Reed module KY-025 |
| | 1 x Obstacle avoidance sensor module KY-032 |
| | 1 x Hunt sensor module KY-033 |
| | 1 x Microphone sound sensor module KY-038 |
| | 1 x Laser sensor module KY-008 |
| | 1 x 5V relay module KY-019 |
| | 1 x Temperature sensor module KY-001 |
| | 1 x Temperature sensor module KY-028 |
| | 1 x Linear magnetic Hall sensors KY-024 |
| | 1 x Flame sensor module KY-026 |
| | 1 x Sensitive microphone sensor module KY-037 |
| | 1 x Temperature and humidity sensor module KY-015 |
| | · |
| | 1 x XY-axis joystick module KY-023 |
| | |
| | 1 x Metal touch sensor module KY-036 |
| | 1 x Arduino 37 Sensor Kit |
| | 1 x Arduino 37 Sensor Kit 1 x Organizer Case |
| 10 | 1 x Arduino 37 Sensor Kit 1 x Organizer Case ZedBoard Zynq-7000 ARM/FPGA SoC Development Board |
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| 10 | 1 x Arduino 37 Sensor Kit 1 x Organizer Case ZedBoard Zynq-7000 ARM/FPGA SoC Development Board Qty: 08 ZedBoard APSoC development board 12 V AC/DC power supply |
| 10 | 1 x Arduino 37 Sensor Kit 1 x Organizer Case ZedBoard Zynq-7000 ARM/FPGA SoC Development Board Qty: 08 ZedBoard APSoC development board 12 V AC/DC power supply 4 GB SD Card USB A to micro-B cable |
| | 1 x Arduino 37 Sensor Kit 1 x Organizer Case ZedBoard Zynq-7000 ARM/FPGA SoC Development Board Qty: 08 ZedBoard APSoC development board 12 V AC/DC power supply 4 GB SD Card USB A to micro-B cable USB Adapter: Male Micro-B to Female Standard-A |
| 10 | 1 x Arduino 37 Sensor Kit 1 x Organizer Case ZedBoard Zynq-7000 ARM/FPGA SoC Development Board Qty: 08 ZedBoard APSoC development board 12 V AC/DC power supply 4 GB SD Card USB A to micro-B cable USB Adapter: Male Micro-B to Female Standard-A PYNQ-Z1: Python Productivity for Zynq-7000 ARM/FPGA SoC with Accessory Kit |
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| | 1 x Arduino 37 Sensor Kit 1 x Organizer Case ZedBoard Zynq-7000 ARM/FPGA SoC Development Board Qty: 08 ZedBoard APSoC development board 12 V AC/DC power supply 4 GB SD Card USB A to micro-B cable USB Adapter: Male Micro-B to Female Standard-A PYNQ-Z1: Python Productivity for Zynq-7000 ARM/FPGA SoC with Accessory Kit Qty: 08 PYNQ-Z1 with Accessory Kit including microSD card |
| | 1 x Arduino 37 Sensor Kit 1 x Organizer Case ZedBoard Zynq-7000 ARM/FPGA SoC Development Board Qty: 08 ZedBoard APSoC development board 12 V AC/DC power supply 4 GB SD Card USB A to micro-B cable USB Adapter: Male Micro-B to Female Standard-A PYNQ-Z1: Python Productivity for Zynq-7000 ARM/FPGA SoC with Accessory Kit Qty: 08 PYNQ-Z1 with Accessory Kit including microSD card Ethernet cable |
| | 1 x Arduino 37 Sensor Kit 1 x Organizer Case ZedBoard Zynq-7000 ARM/FPGA SoC Development Board Qty: 08 ZedBoard APSoC development board 12 V AC/DC power supply 4 GB SD Card USB A to micro-B cable USB Adapter: Male Micro-B to Female Standard-A PYNQ-21: Python Productivity for Zynq-7000 ARM/FPGA SoC with Accessory Kit Qty: 08 PYNQ-Z1 with Accessory Kit including microSD card Ethernet cable micro USB |
| 11 | 1 x Arduino 37 Sensor Kit 1 x Organizer Case ZedBoard Zynq-7000 ARM/FPGA SoC Development Board Qty: 08 ZedBoard APSoC development board 12 V AC/DC power supply 4 GB SD Card USB A to micro-B cable USB Adapter: Male Micro-B to Female Standard-A PYNQ-21: Python Productivity for Zynq-7000 ARM/FPGA SoC with Accessory Kit Qty: 08 PYNQ-Z1 with Accessory Kit including microSD card Ethernet cable micro USB power supply |
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| 11 | 1 x Arduino 37 Sensor Kit 1 x Organizer Case ZedBoard Zynq-7000 ARM/FPGA SoC Development Board Oty: 08 ZedBoard APSoC development board 12 V AC/DC power supply 4 GB SD Card USB A to micro-B cable USB Adapter: Male Micro-B to Female Standard-A PYNQ-Z1: Python Productivity for Zynq-7000 ARM/FPGA SoC with Accessory Kit Oty: 08 PYNQ-Z1 with Accessory Kit including microSD card Ethernet cable micro USB power supply Eclypse Z7: Zynq-7000 SoC Development Board with SYZYGY-compatible Expansion Oty: 1 Eclypse Z7 bundled with a Zmod AWG 1411 and Zmod Scope 1410-105 |
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| 11 | 1 x Arduino 37 Sensor Kit 1 x Organizer Case ZedBoard Zynq-7000 ARM/FPGA SoC Development Board Qty: 08 ZedBoard APSoC development board 12 V AC/DC power supply 4 GB SD Card USB A to micro-B cable USB Adapter: Male Micro-B to Female Standard-A PYNQ-Z1: Python Productivity for Zynq-7000 ARM/FPGA SoC with Accessory Kit Qty: 08 PYNQ-Z1 with Accessory Kit including microSD card Ethernet cable micro USB power supply Eclypse Z7: Zynq-7000 SoC Development Board with SYZYGY-compatible Expansion Qty: 1 Eclypse Z7 bundled with a Zmod AWG 1411 and Zmod Scope 1410-105 ZedBoard Advanced Image Processing Kit (Quad Pcam option) Qty: 5 |
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| 11 | 1 x Arduino 37 Sensor Kit 1 x Organizer Case ZedBoard Zynq-7000 ARM/FPGA SoC Development Board Qty: 08 ZedBoard APSoC development board 12 V AC/DC power supply 4 GB SD Card USB A to micro-B cable USB Adapter: Male Micro-B to Female Standard-A PYNQ-Z1: Python Productivity for Zynq-7000 ARM/FPGA SoC with Accessory Kit Qty: 08 PYNQ-Z1 with Accessory Kit including microSD card Ethernet cable micro USB power supply Eclypse Z7: Zynq-7000 SoC Development Board with SYZYGY-compatible Expansion Qty: 1 Eclypse Z7 bundled with a Zmod AWG 1411 and Zmod Scope 1410-105 ZedBoard Advanced Image Processing Kit (Quad Pcam option) Qty: 5 4 Pcam 5Cs 10 cm ribbon cable |
| 11 12 13 | 1 x Arduino 37 Sensor Kit 1 x Organizer Case ZedBoard Zynq-7000 ARM/FPGA SoC Development Board Qty: 08 ZedBoard APSoC development board 12 V AC/DC power supply 4 GB SD Card USB A to micro-B cable USB Adapter: Male Micro-B to Female Standard-A PYNQ-Z1: Python Productivity for Zynq-7000 ARM/FPGA SoC with Accessory Kit Qty: 08 PYNQ-Z1 with Accessory Kit including microSD card Ethernet cable micro USB power supply Eclypse Z7: Zynq-7000 SoC Development Board with SYZYGY-compatible Expansion Qty: 1 Eclypse Z7 bundled with a Zmod AWG 1411 and Zmod Scope 1410-105 ZedBoard Advanced Image Processing Kit (Quad Pcam option) Qty: 5 4 Pcam 5Cs 10 cm ribbon cable FMC Pcam Adapter |
| 11 | 1 x Arduino 37 Sensor Kit 1 x Organizer Case ZedBoard Zynq-7000 ARM/FPGA SoC Development Board Qty: 08 ZedBoard APSoC development board 12 V AC/DC power supply 4 GB SD Card USB A to micro-B cable USB Adapter: Male Micro-B to Female Standard-A PYNQ-21: Python Productivity for Zynq-7000 ARM/FPGA SoC with Accessory Kit Qty: 08 PYNQ-21 with Accessory Kit including microSD card Ethernet cable micro USB power supply Eclypse 27: Zynq-7000 SoC Development Board with SYZYGY-compatible Expansion Qty: 1 Eclypse 27 bundled with a Zmod AWG 1411 and Zmod Scope 1410-105 ZedBoard Advanced Image Processing Kit (Quad Pcam option) Qty: 5 4 Pcam 5Cs 10 cm ribbon cable FMC Pcam Adapter ZU-5EV (Zynq Ultrascale+ MPSoC Development Board) |
| 11 12 13 | 1 x Arduino 37 Sensor Kit 1 x Organizer Case ZedBoard Zynq-7000 ARM/FPGA SoC Development Board Qty: 08 ZedBoard APSoC development board 12 V AC/DC power supply 4 GB SD Card USB A to micro-B cable USB Adapter: Male Micro-B to Female Standard-A PYNQ-Z1: Python Productivity for Zynq-7000 ARM/FPGA SoC with Accessory Kit Qty: 08 PYNQ-Z1 with Accessory Kit including microSD card Ethernet cable micro USB power supply Eclypse Z7: Zynq-7000 SoC Development Board with SYZYGY-compatible Expansion Qty: 1 Eclypse Z7 bundled with a Zmod AWG 1411 and Zmod Scope 1410-105 ZedBoard Advanced Image Processing Kit (Quad Pcam option) Qty: 5 4 Pcam 5Cs 10 cm ribbon cable FMC Pcam Adapter |
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4 GiB DDR4 SODIMM module

Multimedia: 1.2a dual-lane display port

2x Pcam dual-lane Audio codec H.264/H.265

HDMI

Network connectivity: 2.4 GHz onboard Wi-Fi

Ethernet SIM card slot

WLAN/WWAN/LoRa option: MiniPCle

Expansion:

1x FMC expansion connector

1x FMC gigabit 1x SYZYGY port 4x Pmod ports

15 Xilinx Virtex-7 FPGA VC707 Evaluation Kit

Qty: 1

VC707 evaluation board with the Virtex-7 XC7VX485T2FFG1761CES FPGA

Full-seat ISE Design Suite Logic Edition, device-locked for the Virtex-7 XC7VX485T-2FFG1761CES FPGA

16 Universal Programmer (Xeltek Superpro 610p or equivalent) Oty: 5

Must have support for ~34000 ICs from ~250 manufacturers

Must have In-system programming (ISP / ICP) capability.

Must have Programming / testing features for TTL/CMOS logic ICs and memories.

Must Support devices with Vcc from 1.2V to 5V.

Must be Built with 48 universal pin-drivers.

Must have PC hosted mode

Must support only IC manufacturer approved programming algorithms.

Must have the support for processes such as device selection, file loading, device configuration setting, program option, and batch file setting into one touch step.

Must have the support to set Password for project files and production volume control

Must have Batch command for device operations like program, verify, security into a single command at any sequence.

Must have Serial numbers generators as standard or customer-specific functions.

Must generate a Log file.

Over-current and over-voltage protection for safety of the chip and programmer hardware.

WINDOWS XP/Vista compatibility/Win7/Win10

Supported devices: EPROM, Paged EPROM, Parallel and Serial EEPROM, BPROM, NVRAM, SPLD, CPLD, EPLD, Firmware HUB, Microcontroller, MCU.

Packages supported: DIP, SDIP, PLCC, JLCC, SOIC, QFP, TQFP, PQFP, VQFP, TSOP, SOP, TSOPII, PSOP, TSOP, SOP, TSOPII, PSOP, TSOP, SON, CSP, SCS.

PC interface: USB2.0

Electrical spec. of the AC adapter: AC 100-240V, output 12V/2A; power:15W

Contents:

USB Interfaced Universal Programmer (Xeltek SuperPro 610P or equivalent)

AC Power Adapter

USB Cable

CD with Software

User Manual

17 Zigbee module with antenna (XBee S2C ZigBee (Wire Antenna) or equivalent)

Qty: 10

SPECIFICATION

Interoperable with other ZigBee compliant devices*

Must support binding and multicasting, for easy integration into a Home Automation platform.

15 general-purpose I/O lines

Link budgets of 110 dB for XBee

sleep current of sub 1uA

Firmware upgrades via UART, SPI or over the air Data Rate: RF 250 Kbps, Serial up to 1 Mbps

Indoor/Urban Range: 200ft (60m)

Outdoor/RF Line-of-Sight Range: 4000ft (1200m)

Transmit Power: 3.1mW Receiver Sensitivity: -100dBm Serial Data Interface: UART, SPI

Configuration Method: API or AT command, local or over-the-air

Frequency Band: ISM 2.4GHz

Form Factor: Through-Hole, Surface Mount

Interference Immunity: DSSS (Direct Sequence Spread Spectrum)

ADC Inputs: (4) 10-bit ADC inputs

Digital I/O: 15

Antenna: Integrated Wire

| Chairs | |
|---|-------|
| QTY: 40 | |
| Office Chair (Ergonomic Desk Chair Mesh | |
| Computer Chair). | |
| | |
| Material: Fabric Padded Seat | |
| Base: Nylon | |
| Arms: Polyurethane (PU) | |
| | |
| Mesh back: breathable mesh back | / / / |
| provides ventilation while seated | |
| Built-in Lumbar support | |
| Tilt Mechanism: torsion bar basic | |
| tilting mechanism | |
| Nylon Base: durable nylon base wit | h |
| castor wheels for 360° rotation | |
| Height Adjustable: gas lift mechani | sm |
| 5 5 | A |
| | |

| Lot No. 8 | 3: Intelligent Biomedical Lab | | |
|-------------------------------------|---|--|--|
| 1 | BIOPAC (Data Acquisition System for Biomedical Engineering) | | |
| 1 | Quantity: 01 | | |
| | Power: | Data Acquisition Unit with USB Cable, DC Adapter (110V/60Hz or 220V/50Hz) & Cord (Hospital Grade) Technical Specification of the Data Acquisition Unit | |
| | Number of Channels: | Isolated human-safe universal input amplifiers: 4 Channels | |
| | A/D Sampling Resolution: | 24-bit | |
| | Gain Ranges: | 5x to 50,000x (13 steps) | |
| | Input Voltage Range: | Adjustable from ± 200 μV to ± 2 V | |
| | Signal-to-Noise Ratio | > 89 dB min | |
| | Input Noise Voltage: | 0.1 μV rms noise (0.1 Hz to 35 Hz) – nominal | |
| | Input Noise Current: | 2.1 pA rms (0.1 Hz to 10 Hz) - nominal | |
| | CMRR: | 85 dB minimum | |
| | Software Filters: | Three programmable digital (IIR) filters; automatic or user-adjustable | |
| | Hardware Filters: | Low pass – 20 KHz | |
| | | High pass – DC, 0.05 Hz, 0.5 Hz, 5 Hz | |
| | Channel-to-Channel Latency: | None: Channels are sampled simultaneously | |
| | Analog Output | ± 0.5 V output Headphone jack 3.5 mm stereo jack connection | |
| | Sample Rate: | 100,000 samples/sec each channel | |
| | Serial Interface Type: | USB 2.0 full speed | |
| | Certification: | Complies with IEC 60601-1 EMC complies with IEC 60601-1-2 CE Marked | |
| | Analog Output: | Back panel DUSB 9m labeled "Analog Out" | |
| | Voltage Output: | Range -10 V to +10 V Resolution: 16-bits | |
| | Pulse Output: | variable, 50 μsec – 100 msec | |
| | Width: | | |
| | Repetition: | variable. 100 μsec – 5 seconds | |
| | Pulse Level: | Adjustable from -10 V to +10 V With BSLSTMB Stimulator: 0 – 100 V | |
| | Electrode Check: | Impedance Range 0-1 MΩ (Checks Impedance between Vin+ and GND, Vin- and GND) Input Triggering Options | |
| | External Trigger: | Back panel BNC labeled "Trigger" TTL positive or negative edge | |
| | Analog Trigger: | Any Input channel (front panel "CH1 – CH4") | |
| | Digital Trigger: | Any of the eight input lines (back panel DSUB 25m) | |
| | Accessories | | |
| | 2 x Electrode Lead Sets – | | |
| | Disposable Electrodes (100/pk) – | | |
| | Abrasive Pads (10/pk) – | | |
| | Hand Dynamometer – | | |
| | BP Cuff Transducer – | | |
| Electronic Stethoscope Transducer – | | | |
| 1 | Air Flow Transducer, factory-calibrated – Disposable Filtered Mouthpieces (10/pk) – | | |
| | | | |

| | Disposable Noseclips (10/pk) – | | | |
|---|--|--------------------------------------|--|--|
| | Hand Switch – | | | |
| | Headphones – | | | |
| | Pulse Transducer – | | | |
| | Signal Processing Breadboard Kit – | | | |
| | Breadboard Accessories – | | | |
| | | | | |
| | breadboard interface – | | | |
| | Electronic Breadboard Probe – | | | |
| | exercise physiology & biomechanics | | | |
| | Development Kit: | | | |
| | Exercise Physiology & Biomechanics Kit: | | | |
| | Features: | | | |
| | · ECG, EEG, EMG, EOG & EGG | | | |
| | · Respiration | | | |
| | · Temperature | | | |
| | Airflow & Lung Volume | | | |
| | · Cardiac Output (via bioimpedance) | | | |
| | · Respiratory Exchange Ratio | | | |
| | · Basal or Resting Metabolic Rate | | | |
| | Motor Unit Recruitment | | | |
| | · 12-Lead ECG | | | |
| | · Heart Sounds | | | |
| | · Blood Pressure | | | |
| | · Stroke Volume | | | |
| | Gait Analysis (including Heel-Toe Strik | (م | | |
| | Range of Motion Acceleration, Veloci | | | |
| | | ty, distance | | |
| | Biomed Engineering Kit: | | | |
| | Features: | | | |
| | · Signal Analysis & Processing | | | |
| | • ECG, EDA (GSR), EEG, EGG, EMG & EC | | | |
| | · Force, Pressure, Strain, Flow, Tempera | ature, Sound, Light | | |
| | · Filters (FIR & IIR) | | | |
| | · Instrumentation Design | | | |
| | · Respiratory System & Pulmonary Fun | | | |
| | · Bioimpedance (Cardiac Output & Bloo | , | | |
| | · Biomechanics—Angle, Acceleration, I | Distance, Velocity | | |
| | · Transducers & Calibration | | | |
| | Physiological Control Systems | | | |
| | Compartmental Modeling of Blood Presented | | | |
| | · Gait Analysis Chart, Overlap, Scope & | X/Y Displays | | |
| | · Spectral Analysis & Histograms | | | |
| | | | | |
| | Freestyle Libre 2 Reader with Sensor - Continuous Glucose Monitor (Starter Pack) | | | |
| 2 | Quantity: 2 | | | |
| | | | | |
| | Model | FreeStyle Libre 2 Reader with Sensor | | |
| | Brand | FreeStyle Libre 2 Reader with Sensor | | |
| | | | | |
| | Myo gesture control armband | | | |
| | Quantity: 2 (white) | | | |
| 3 | | | | |
| | Electrode | Eight | | |
| | | 9-axes inertial measurement unit | | |
| | | | | |
| | Measurements | Transmission module | | |

| 4 | MyoWare 2.0 Muscle Sensor Developmen | | | |
|---|--|---|--|--|
| | | t Kit With complete sensors and accessories | | |
| | Sparkfun Product ID: 18441 | | | |
| | 2.2 Inch Flex Sensor | Quantity: 20 | | |
| | Technical Specification: | | | |
| | • Resistance in straight state: 25K ohm | | | |
| 5 | • Resistance value tolerance: ±30% | | | |
| | Bending resistance change: 60K ~110K | ohm | | |
| | Rated power: 0.5 watts | | | |
| | • Peak power: 1 watt | | | |
| | Bending life: >1 million times | | | |
| | • Working temperature: -35°C ~ +80°C | | | |
| | • Length x width: 73.66x6.35mm | | | |
| | Interface type: 2-Pin metal pins (pitch 0.1") | | | |
| | MySignals HW BLE Complete Kit (eHealth Medical Development Platform for Arduino) | | | |
| | , | | | |
| | Quantity: 1 | | | |
| | | Snore, Spirometer, Blood Pressure (BLE), SPO2 (BLE), Glucometer (BLE) and Body Scale (weight, | | |
| | Sensor | bone mass, body fat, muscle mass, body water, | | |
| | | visceral fat, Basal Metabolic Rate and Body Mass | | |
| 6 | | Index). | | |
| | Architecture | Arduino compatible | | |
| | RAM Memory | 2K | | |
| | Flash Memory | 32K | | |
| | Screen | TFT (basic graphics) | | |
| | Concurrent Sensor Readings | From one group of sensors (analog, UART, BLE) to one interface (TFT, BLE, WiFi) | | |
| | Radios on board | BLE, WiFi | | |

| Lot No. 9: Computer Vision Lab | | | | | |
|--------------------------------|--|--|--|--|--|
| 1 | Jetson Orin Nano Developer Kit Quantity: 4 | | | | |
| | Key Features: Developer Kit Content (P3766) > Jetson Orin Nano™ 8GB module with heat sink and reference carrier board > DC Power Supply > 802.11ac/abgn wireless network interface controller > Quick Start Guide | | | | |
| 2 | Jetson AGX Orin 64GB Developer Kit Quantity: 4 | | | | |
| | Key Features: Jetson AGX Orin 64GB module > 2048-core NVIDIA Ampere architecture GPU with 64GB tensor cores > 12-core Arm® Cortex®-A78AE v8.2 64-bit CPU > 2x NVDLA v2.0 > PVA v2.0 > 64GB 256-bit LPDDR5 > 64GB eMMC 5.1 | | | | |
| | Jetson TX2 NX Module Quantity: 4 | | | | |
| 3 | Key Features: > NVIDIA Pascal™ architecture with 256 NVIDIA® CUDA® cores > Dual-core NVIDIA Denver 2 64-bit CPU and quad-core Arm® Cortex®-A57 MPCore processor complex > 4GB 128-bit LPDDR4 > 16GB eMMC 5.1 > 10/100/1000 Base-T Ethernet Power > Voltage Input: 5V > Module Power: 7.5W -15W | | | | |

Note:

- 1. PAF-IAST may re-adjust the quantities specified against the specifications of same genre in any of the Lots or increase the quantities as permissible under PPRA Rules.
- 2. The Bidder shall indicate in their offer,
 - a. detailed specifications of their offered product(s),
 - b. standard accessories,
 - c. make and origin, as part of confirming Compliance as per the format given in Form D.
- 3. The Unit Price, Total Bid Price, and Additional Warranty Price of the quoted items shall be indicated as per the given format in Form G.
- 4. Bidders are required to provide/attach third party report or assessment in case items are quoted as per the provision of "Equivalent" given in RFP

Section 5b: Special Terms and Conditions

Standard

- The goods supplied must be capable of functioning properly under the climatic conditions of Haripur.
- There shall be no deviation from specification and country of make as provided with each item. In case of any ambiguity in specification/ accessories needed for the full functioning of the equipment, the firm must clear it with the Procurement Committee. However, the decision of the Procurement Committee will be final.
- The goods with standard accessories supplied under this tender shall confirm to the standard maintenance in the technical specification.
- Visit to already installed and operational equipment if required as per Section 5, shall be provided within the time specified and unless otherwise specified by the Purchaser, at no expense to the Institute. The PAF-IAST may ask the bidders to carry out testing/analysis of samples (to be provided) to evaluate the performance of already installed and operational unit of similar specifications.

Training

• The firm supplying the item/ equipment(s) will demonstrate the operation/ working of the supplied goods to the satisfaction of PAF- IAST and provide training. Suppliers are advised to provide details on formal training for the LOT(s) covering aspects as mentioned below, but not limited to, as required in Form – E (Section 3).

| LOT(s) | | |
|----------|--|--|
| Level | 1 to 9 | |
| Basic | Demonstrate the operations/ working to end users; Identify the do's and don'ts; and aspects deem necessary for long-life functioning of supplied goods. | |
| Hands-on | Demonstrate technical features; Elaborate technical configuration(s) performed for integration with the overall setup; Documented guidelines for generating reports using software and/or systems' interface | |
| Advanced | Provide trainings to Operators for troubleshooting and smooth operations using system manuals | |

• The Bidder shall be responsible for all the necessary training programs available for the operation, maintenance and troubleshooting of the equipment at no additional cost to the institute. Unless otherwise specified, such training as well as training materials shall be provided in the language of the Bid as specified in the BDS.

Calibration of item/equipment

• The supplier will install the good(s) in the presence and satisfaction of the Procurement Committee, if need be. In case of any defect in the supplied good(s) or if it is not in accordance with the desired specification(s), the goods will be changed at the cost of the supplier.

Warranty/ Guarantee

- The Supplier will give comprehensive onsite warranty/ guarantee that the goods/ stores/ articles would continue to conform to the description and quality as specified for a period of at least One (01) year and additional two (02) years as Extended Warranty from the date of delivery, installation and commissioning of the said goods/ stores/ articles to be purchased and that notwithstanding the fact that the purchaser may have inspected and/ or approved the said goods/ stores/ article, if during the aforesaid period, the said goods/ stores/ articles, be discovered not to conform to the description and quality aforesaid or have determined (and the decision of the Procurement Committee in that context will be final and conclusive), the PAF: IAST will be entitled to reject the said goods/ stores/ articles or such portion thereof as may be discovered not to conform to the said description and quality, on such rejection the goods/ articles/ stores will be at the supplier's risk and all the provisions relating to rejection of goods etc. shall apply.
- The Supplier shall, if so called upon to do, replace the goods etc., or such portion thereof as is rejected by Procurement Committee, otherwise the supplier shall pay such damage as may arise by the reason of the breach of the condition herein contained. Nothing herein contained shall prejudice any other right of the Procurement Committee in that behalf under this contract or otherwise.
- The Supplier shall also replace equipment, in case it is found defective which cannot be put to operation due to manufacturing defect, etc. In case of equipment specified by the Procurement Committee, the supplier shall be responsible from carrying out annual maintenance and repairs on the terms and conditions as may be agreed. The supplier shall also be responsible to ensure adequate regular supply of spare parts needed for a specific type of equipment whether under their annual maintenance and repairs contract or otherwise. In case of change of model, supplier will give sufficient notice to the Procurement Committee who may like to purchase spare parts from them to maintain the equipment in perfect condition.

Section 6: Returnable Bidding Forms / Checklist

This section serves as a checklist for preparation of your Bid. Please complete the Returnable Bidding Forms in accordance with the instructions in the forms and return them as part of your Bid submission. No alteration to format of forms shall be permitted and no substitution shall be accepted.

Before submitting your Bid, please ensure compliance with the Bid Submission instructions of the BDS 22.

Bid Proposal:

| Have you duly completed all the Returnable Bidding Forms? | |
|---|--|
| Form A: Bid Submission Form | |
| Form B: Joint Venture/Consortium/ Association Information Form | |
| Form C: Bidder Information Form | |
| Form D: Qualification Form | |
| Form E: Bid Proposal Form | |
| Form F: Specifications Compliance Form | |
| Form G: Price Schedule Form | |
| Have you provided the required documents to establish compliance with the | |
| evaluation criteria in Section 4? | |

Form A: Bid Submission Form

(To be Submitted in an envelope duly sealed and marked as Technical Proposal)

| Name of Bidder: | [Insert Name of Bidder] | Date: | Select date |
|-----------------|--------------------------|-------|-------------|
| ITB reference: | PAF: IAST-AIE-ITB-114-21 | | |

We, the undersigned, submit our Bid for the award of contract to supply the goods and related services required for [Insert Title of goods and services] in accordance with your Invitation to Bid No. [Insert ITB Reference Number]. We hereby submit our Bid, which includes this Bid proposal.

We hereby declare that our firm, its affiliates or subsidiaries or employees, including any JV/ Consortium/ Association members or subcontractors or suppliers for any part of the contract:

- a) is not under procurement prohibition by any of the Government/ Semi-government/ Autonomous organization;
- b) have not been suspended, debarred, sanctioned or otherwise identified as ineligible by any Organization in Pakistan;
- c) have not declared bankruptcy, are not involved in bankruptcy or receivership proceedings, and there is no judgment or pending legal action against us that could impair our operations in the foreseeable future;
- d) undertake not to engage in proscribed practices, including but not limited to corruption, fraud, coercion, collusion, obstruction, or any other unethical practice, with the PAF: IAST, and to conduct business in a manner that averts any financial, operational, reputational or other undue risk to the PAF: IAST.

We declare that all the information and statements made in this Bid are true and we accept that any misinterpretation or misrepresentation contained in this Bid may lead to our disqualification and/ or sanctioning by the PAF-IAST.

We offer to supply the goods and related services in conformity with the Bidding documents, including the PAF-IAST General Conditions of Contract and in accordance with the Schedule of Requirements and Specifications.

Our Bid shall be valid and remain binding upon us for the period specified in the Bid Data Sheet.

We understand and recognize that you are not bound to accept any Bid you receive.

I, the undersigned, certify that I am duly authorized by [Insert Name of Bidder] to sign this Bid and bind it should PAF- IAST accept this Bid.

| Name: | | | |
|------------|------|------|-------|
| Title: | | | _ |
| Date: | | | _ |
| Signature: | | | |

[Stamp with official stamp of the Bidder]

Form B: Joint Venture/ Consortium/ Association Information Form

(To be Submitted in an envelope duly sealed and marked as Technical Proposal)

| Name | e of Bidder: | [Insert Name of Bidd | , | ica as ream | Date: | Select date | | |
|--|---|--|-------|---------------|-----------|--|--|--|
| ITB re | eference: | erence: PAF: IAST-AIE-ITB-114-21 | | | | | | |
| | To be completed and returned with your Bid if the Bid is submitted as a Joint Venture/Consortium/Association. | | | | | | | |
| No | | ner and contact ir rs, fax numbers, e-mail o | | | type of g | on of responsibilities (in goods and/or services to be performed | | |
| 1 | [Complete] | | | [Complete] | | | | |
| 2 | [Complete] | | | [Complete] | | | | |
| 3 | [Complete] | | | [Complete] | | | | |
| Associ event execu We have likely lo | a Contract is award ition) we attached a copy | e JV, Consortium, B process and, in the led, during contract y of the below referen nd the confirmation o | | | | | | |
| □ Letter of intent to form a joint venture <i>OR</i> □ JV/Consortium/Association agreement We hereby confirm that if the contract is awarded, all parties of the Joint Venture/Consortium/Association shall be jointly and severally liable to PAF: IAST for the fulfillment of the provisions of the Contract. | | | | | | | | |
| | | | | e of partner: | | | | |
| | ure: | | | | | | | |
| Date: | | | Date: | | | | | |

Form C: Bidder Information Form

Does your organization demonstrates significant commitment to sustainability through some other means, for example internal company policy documents on

empowerment, renewable energies, education, vocational trainings, social responsibility towards people with Special needs, or membership of trade institutions promoting such issues

women

(To be Submitted in an envelope duly sealed and marked as Technical Proposal)

| Name of Bidder: | [Insert Name of Bi | dder] | Da | ate: | Select date |
|--|---------------------------------|--|----|------|-------------|
| ITB reference: | PAF: IAST-AIE-ITB-: | 114-21 | | | |
| | | | | | |
| Legal name of Bidder | | [Complete] | | | |
| Legal address & Branci | h Offices | [Complete] | | | |
| Year of registration Bidder's Authorized Re Information | epresentative | [Complete] Name and Title: [Complete] Telephone numbers: [Complemail: [Complete] | | | |
| Are you a PAF: IAST registered vendor? | | ☐ Yes ☐ No If yes, [insert PAF- IAST vendor number] | | | |
| Countries of operation | | [Complete] | | | |
| No. of full-time emplo | yees | [Complete] | | | |
| No. of Technical Staff Quality Assurance Cer 9000 or Equivalent) (If of the valid Certificate): | | [Complete] | | | |
| Does your Comp accreditation such as 14064 or equivalent environment? (If yes, p valid Certificate): | ISO 14001 or ISO related to the | [Complete] | | | |
| Does your Company has Statement of its Environment of Company? (If yes, provide a | onmental | [Complete] | | | |

[Complete]

| Contact person that DAE: IAST may contact | Name and Title: [Complete] |
|--|--|
| Contact person that PAF: IAST may contact for requests for clarifications during Bid evaluation (Only Lead Bidder) | Telephone numbers: [Complete] Email: [Complete] |
| Please attach the following documents: | |
| | Company Profile, which should not exceed fifteen (15) pages, including printed brochures and product catalogues relevant to the goods and/ or services being procured. |
| | Proposed timetable for delivery, installation and commissioning plan for the required and quoted items to PAF: IAST after the award of Contract. |
| | 3. Certificate of Registration of the business. |
| | 4. Principal's Authorization Letter in favor of Bidder to participate in this Tender. |
| | 5. A proofing document confirms the offered warranty for at least One (01) year, supported by the manufacturer's certificates, if applicable. |
| | A proofing document confirming supply of same or similar items of this magnitude to various clients/ customers in Pakistan. |
| | Proven records of no less than the required Projects of similar nature/ value/ complexity in which delivery and services were extended. |
| | 8. Full detailed description of the specifications of the proposed items in addition to catalogues clearly showing the proposed specifications responding to the requirements. |
| | 9. Supporting photos of the proposed items, if applicable. |
| | 10. Quality certifications: ISO 9001:2015 (if applicable) |
| | 11. Latest Audited Financial Statements (Income Statement and Balance Sheet) including Auditor's Report for the past (3 years). |

Note: To be filled in by each partner in case Bid is submitted as a JV/ Consortium/ Association

Form D: Qualification Form

(To be submitted in an envelope duly sealed and marked as Technical Proposal)

| Name of Bidder: | [Insert Name of Bidder] | Date: | Select date |
|-----------------|--------------------------|-------|-------------|
| ITB reference: | PAF: IAST-AIE-ITB-114-21 | | |

If JV/ Consortium/ Association, to be completed by each partner.

PREVIOUS RELEVANT EXPERIENCE

Please list all Projects successfully completed in the last 3 years, covering following aspects; a) Scope of the projects/ assignments.

- b) Activities performed for the successful completion of the project.
- c) Support Services Contracts in hand with SLA for the supplied goods.

List only those assignments for which the Bidder was legally contracted or sub-contracted by the Client as a company or was one of the Consortium/ JV partners. Assignments completed by the Bidder's individual experts working privately or through other firms cannot be claimed as the relevant experience of the Bidder, or that of the Bidder's partners or sub-consultants, but can be claimed by the Experts themselves in their CVs. The Bidder should be prepared to substantiate the claimed experience by presenting copies of relevant documents and references if so requested by PAF- IAST.

| Project name & Country of Assignment | Client & Reference Contact Details | Contract Value | Period of activity and status | Types of activities undertaken |
|--|---------------------------------------|----------------|-------------------------------|--------------------------------|
| | | | | |
| | | | | |
| | | | | |

Bidders may also attach their own Project Data Sheets with more details for assignments above.

HISTORY OF NON-PERFORMING CONTRACTS

| ☐ Non-perf | orming contracts did r | not occur during the last 3 years | |
|------------|------------------------------------|---|--|
| ☐ Contract | (s) not performed in th | ie last 3 years | |
| Year | Non- performed portion of contract | Contract Identification | Total Contract Amount (current value in US\$) |
| | | Name of Client: Address of Client: Reason(s) for non-performance: | |

FINANCIAL STANDING

| Annual Turnover for the last 3 years | Year | PKR |
|---|------|-----|
| | Year | PKR |
| | Year | PKR |
| Latest Credit Rating (if any), indicate the | | |
| source | | |

| Financial information (in PKR equivalent) | Historic information for the last 3 years | | | |
|--|---|----------------------------|--------|--|
| | Year 1 | Year 2 | Year 3 | |
| | In | formation from Balance She | eet | |
| Total Assets (TA) | | | | |
| Total Liabilities (TL) | | | | |
| Current Assets (CA) | | | | |
| Current Liabilities (CL) | | | | |
| | Information from Income Statement | | | |
| Total / Gross Revenue (TR) | | | | |
| Profits Before Taxes (PBT) | | | | |
| Net Profit | | | | |
| Current Ratio | | | | |

☐ Attached are copies of the audited financial statements (balance sheets, including all related notes, and income statements) for the years required above complying with the following condition:

- a) Must reflect the financial situation of the Bidder or party to a JV, and not sister or parent companies;
- b) Historic financial statements must be audited by a certified public accountant;
- c) Historic financial statements must correspond to accounting periods already completed and audited. No statements for partial periods shall be accepted.

Form E: Technical Bid Proposal Form

(To be submitted in an envelope duly sealed and marked as Technical Proposal)

| Name of Bidder: | [Insert Name of Bidder] | Date: | Select date |
|-----------------|--------------------------|-------|-------------|
| ITB reference: | PAF: IAST-AIE-ITB-114-21 | | |

The Bidder's Bid should be organized to follow this format of the Technical Bid Proposal. Where the bidder is presented with a requirement or asked to use a specific approach, the bidder must not only state its acceptance, but also describe how it intends to comply with the requirements. Where a descriptive response is requested, failure to provide the same may be viewed as non-responsive.

SECTION 1: Qualification, capacity and expertise

- 1.1 Bidder's general organizational capability: management structure, financial stability and project financing capacity, project management controls, extent of work to be subcontracted (if so, provide details).
- 1.2 Bidder's relevance of specialized knowledge and experience on similar engagements done in the region/ country. Bidder should submit a detailed description of the projects executed (quantities, value, beneficiary)
- 1.3 Manufacturer's strengths covering the regional/ global market presence, hi-tech products portfolio, manufacturing capacity, R&D activities resulting in national and international patents, quality control and assurance practices, and international certifications in relevant areas.

SECTION 2: Management Structure and Key Personnel

- 2.1 Describe the overall management approach toward planning and implementing the project. Include an organization chart for the management of project describing relationship of key positions and designations.
- 2.2 Provide CVs for key personnel that will be provided to support the implementation of this project using the format below. CVs should demonstrate qualifications in areas relevant to scope of goods and/or services.

Format for CV of Proposed Key Personnel

| Name of Personnel | [Insert] |
|-------------------------------|---|
| Position | [Insert] |
| Nationality | [Insert] |
| Language proficiency | [Insert] |
| Education/ | [Summarize college/university and other specialized education of personnel member, giving names of schools, dates attended, and degrees/qualifications obtained.] |
| Qualifications | [Insert] |
| | [Provide details of professional certifications relevant to the scope of goods and/or services] |
| Professional certifications | + Name of institution: [Insert]+ Date of certification: [Insert] |
| Employment Record/ Experience | [List all positions held by personnel (starting with present position, list in reverse order), giving dates, names of employing organization, title of position and location of employment. |
| pario | [Insert] |
| = - | that to the best of my knowledge and belief, the data provided above correctly s, my experiences, and other relevant information about myself. |
| Signature of Personnel | Date (Day/Month/Year) |

SECTION 3: Scope of Supply, Technical Specifications and Training(s)

This section should demonstrate the Bidder's responsiveness to the specification by identifying the specific components proposed, addressing the requirements, as specified, point by point; providing a detailed description of the essential performance characteristics proposed; and demonstrating how the proposed bid meets or exceeds the requirements/specifications. All important aspects should be addressed in sufficient detail.

- 3.1 A detailed description of how the Bidder will deliver the required goods and services, keeping in mind the appropriateness to local conditions and project environment. Details how the different service elements shall be organized, controlled and delivered.
- 3.2 Explain whether any work would be subcontracted, to whom, how much percentage of the requirements, the rationale for such, and the roles of the proposed sub-contractors and how everyone will function as a team.
- 3.3 Implementation plan including a Gantt Chart or Project Schedule indicating the detailed sequence of activities that will be undertaken and their corresponding timing.
- 3.4 Details on post-deployment trainings on-site hands-on training for all LOTs.

SECTION 4: Registration & Certifications

This section should demonstrate the Bidder's responsiveness towards its registration with the relevant national body and international organizations Certifying the bidder's qualifications with respect to Quality and Project Management.

- 4.1 Provide a copy of valid registration with the Pakistan Engineering Council (if applicable).
- 4.2 Provide a copy of valid Certificate issued by International Organization for Standardization certifying the bidder's compliance and practices towards quality management principles and standards in their offered products/ solutions and services.
- 4.3 Provide a copy of valid Certificate issued by International Organization for Standardization certifying the bidder's compliance and practices towards information security management principles and standards in their offered products/ solutions and services.

SECTION 5: Warranty and Support Services

This section should demonstrate the Bidder's responsiveness to the post-commissioning warranty and support services of the goods supplied, addressing the requirements, as specified, point by point; providing a detailed description of the essential performance characteristics proposed; and demonstrating how the proposed bid meets or exceeds the requirements. All important aspects should be addressed in sufficient detail.

- 5.1 A detailed description of how the Bidder will provide the Warranty claims to the users, keeping in mind the span and complexity of the project in context of local conditions and project environment.
- 5.2 Explain whether any services or work would be subcontracted, to whom, how much percentage of the requirements, the rationale for such, and the roles of the proposed subcontractors and how everyone will function as a team.
- 5.3 Details how the post-delivery/ deployment Support Services will be provided to the users keeping in consideration the criticality of systems, and dependency of university administration and operations on such systems.

Form F: Specifications Compliance Form

(To be submitted in an envelope duly sealed and marked as Technical Proposal)

| Name of Bidder: | [Insert Name of Bidder] | Date: | Select date |
|-----------------|--------------------------|-------|-------------|
| ITB reference: | PAF: IAST-AIE-ITB-114-21 | | |

The Bidder's Bid should be organized to follow this format of the Technical Bid Proposal. Where the bidder is presented with a requirement or asked to use a specific approach, the bidder must not only state its acceptance, but also describe how it intends to comply with the requirements. Where a descriptive response is requested, failure to provide the same may be viewed as non-responsive.

| | | | Your response Compliance with specifications | |
|--------------|---|---------------------|--|--|
| (based on th | services to be Supplied e Technical Specifications Section 5a & Section 5b) | Comply (Yes/ No) | Quoted Specifications | Type/ Model no. & Country of Origin |
| Required Ite | ms | | Offered Items | |
| | Lot i | #1 Customize | ed Multi-copters Agile Drone | |
| 1. | Custom-Build Agile Multi-copter | | | |
| 2. | RTK-GNSS Base station (Here+V2 or Equivalent) | | | |
| 3. | Extra Aerial & Ground Batteries | | | |
| | Lot # | 2 Customized | d Multi-copters Carrier Drone | |
| 1. | Custom-Built Carrier Multi-copter | | | |
| 2. | RTK-GNSS Base station (Here+V2 or Equivalent) | | | |
| 3. | Extra Aerial & Ground Batteries | | | |
| | LC | DT #3: Drone | Swarm and Safety Net | |
| 1. | Flame-Retardant Drone Safety Net (Custom-Made) 30 x 100 Feet | | | |
| 2. | Flame-Retardant Drone Safety Net (Custom-Made) 25 x 25 Feet | | | |
| 3. | Loco swarm bundle inclusive additional highlighted accessories | | | |
| 4. | Drone DJI Mavic 3 Pro or equivalent | | | |

| Lot #4: Field Robotics Lab | | | | | |
|----------------------------|--|----------------|------------------------|--|--|
| 1 | Unmanned ground vehicle: [Segway RMPLite 220 or equivalent] | | | | |
| 2 | Modern Manipulator Arm QArm – Quanser or Equivalent | | | | |
| | L | ot #5: IoT, Se | nsors and IT Equipment | | |
| 1 | Arduino Edge Control | | | | |
| 2 | Arduino Explore IoT Kit | | | | |
| 3 | EMoRo 2560 Controller | | | | |
| 4 | ARDUINO UNO WiFi REV2 | | | | |
| 5 | USB 2.0 Cable Type A/B | | | | |
| 6 | Soldering Stand: QuadHands Classic Helping Hands Tool | | | | |
| 7 | High Precision Barometric Pressure Sensor Grove(DPS310) or equivalent | | | | |
| 8 | Gravity: UART Infrared CO2 Sensor (0- 50000ppm) | | | | |
| 9 | Grove - Gas Sensor (MQ3) | | | | |
| 10 | Gravity: Analog CO2 Gas Sensor (MG-811 Sensor) | | | | |
| 11 | Gravity: Analog Capacitive Soil Moisture Sensor - Corrosion Resistant | | | | |
| 12 | Digital Infrared Temperature Sensor (Grove or equivalent) | | | | |
| 13 | Multi-function Environmental Module - CCS811+BME280 | | | | |
| 14 | Gravity: Non-contact Digital Water / Liquid Level Sensor For Arduino | | | | |
| 15 | Air Quality Sensor (CCS811 DFRobot or equivalent) | | | | |
| 16 | Water Sensor (Grove or equivalent) | | | | |

| _ | | | _ |
|----|---|--|---|
| 17 | Temperature Sensor (Grove or equivalent) | | |
| 18 | Temp & Humidity & Barometer Sensor (BME280 Grove or equivalent) | | |
| 19 | Moisture Sensor (Grove or equivalent) | | |
| 20 | Hall Sensor (Grove or equivalent) | | |
| 21 | Analog pH Sensor / Meter Pro Kit For Arduino (Gravity or equivalent) | | |
| 22 | Ozone Sensor (0- 10ppm) (Gravity or equivalent) | | |
| 23 | SOIL HUMIDITY SENSOR, WATERMARK 2 M / 75 CM (Pack of 6) | | |
| 24 | Arduino Nano 33 IoT with headers | | |
| 25 | WiFi Module - ESP8266 (4MB Flash) | | |
| 26 | ESP-01S Wifi Module with relay or equivalent | | |
| 27 | Fingerprint Sensor Module (Adafruit or equivalent) | | |
| 28 | Adafruit DS1307 Real Time Clock Assembled Breakout Board | | |
| 29 | DS3231 Precision RTC Breakout (Adafruit or equivalent) | | |
| 30 | MicroSD card breakout board+(Adafruit or equivalent) | | |
| 31 | HDMI Cables for Raspberry Pi 4 B+ (Micro HDMI to HDMI) | | |
| 32 | Hot Air Soldering Rework Station w/ Three Nozzles – Quick 957DW+ | | |
| 33 | Engineer Professional Silicone-Tip Solder Sucker | | |
| 34 | ATTEN 80W 110V Soldering Iron With Station - ST-2090D | | |

| | 128 GB Extreme | | | |
|-----|------------------------------------|------------|-----------------|--|
| 35 | microSDHC UHS-I | | | |
| 33 | Memory Card with | | | |
| | Adapter or equivalent | | | |
| 36 | Mira Ctrimpar | | | |
| 30 | Wire Stripper | | | |
| | Breadboard power | | | |
| 37 | supply | | | |
| | | | | |
| 38 | Vero Board | | | |
| | Magnifying glass for | | | |
| 39 | soldering | | | |
| | | | | |
| 40 | Breadboard | | | |
| | RAM - 16GB DDR4 | | | |
| 41 | 3200MHz SODIMM | | | |
| 7- | PC4-25600 | | | |
| | SATA 2.5" SSD 512GB | | | |
| 42 | for laptops | | | |
| | Tot Tuptops | | | |
| 43 | Keyboards | | | |
| | | | | |
| | | LOT #6: E1 | mbedded Systems | |
| | WiFi LoRa 32 Dev | | | |
| 1 | Board (Heltec or | | | |
| | equivalent) | | | |
| | LoRa Test Board Kit | | | |
| 2 | (LLCC68 based E220- | | | |
| | 900T30S or equivalent) | | | |
| _ | LoRa LLCC68 | | | |
| 3 | Development Kit 430 MHz 470 MHz | | | |
| | LLCC68 LoRa Module | | | |
| 4 | 868MHz 915MHz | | | |
| 4 | 30dBm UART | | | |
| | LLCC68 LoRa Module | | | |
| 5 | 433MHz 470MHz | | | |
| , | 30dBm UART | | | |
| | Antenna for LLCC68 | | | |
| 6 | LoRa Module 868MHz | | | |
| | 915MHz 30dBm UART | | | |
| | DE1-SoC Development | | | |
| 7 | Kit including cables | | | |
| | and power adapter | | | |
| | | | | |
| 8 | DE10 Lite | | | |
| | Super Value Ultimate | | | |
| 9 | 37 in 1 Sensor Modules | | | |
| | Kit for Arduino & MCU | | | |
| | ZedBoard Zynq-7000 | | | |
| 10 | ARM/FPGA SoC | | | |
| | Development Board | | | |
| 4.6 | PYNQ-Z1: Python | | | |
| 11 | Productivity for Zynq- | | | |
| | | | | |

| 7000 ARM/FPGA SoC with Accessory Kit Eclypse Z7: Zynq-7000 SoC Development Board with SYZYGY- compatible Expansion ZedBoard Advanced Image Processing Kit (Quad Pcam option) 2U-SEV (Zynq 14 Ultrascalet MPSoC Development Board) 15 Xillinx Virtex-7 FPGA CYOT Evaluation Kit Universal Programmer (Xeltek Superpro 610p or equivalent) 2ighee module with antenna (XBee SZC Zighee (Wire Antenna) or equivalent) 17 Actions Lot #8: Intelligent Biomedical Lab BIOPAC (Data Acquisition System for Biomedical Engineering) Freestyle Libre 2 Reader with Sensor- Continuous Glucose Monitor (Starter Pack) 3 Myo gesture control armband MyWare 2.0 Muscle Sensor Development Kit 5 2.2 Inch Flex Sensor MySignals HW BLE Complete Kit (Health Medical Development Platform for Arduino) Lot #9: Computer Vision Lab 1 Jetson Orin Nano Developer Kit 2 Developer Kit 2 Developer Kit 3 Jetson AGX Orin 64GB Developer Kit 2 Developer Kit 3 Jetson AGX Orin 64GB Developer Kit 3 Jetson AGX Orin 64GB Developer Kit 3 Jetson AGX Orin 64GB Developer Kit 3 Jetson TX2 NX Module | | 7000 ADNA/EDCA 5-6 | | | |
|--|----|---|---------------|-------------------------|--|
| SoC Development Board with SYZYGY- compatible Expansion ZedBoard Advanced Image Processing Kit (Quad Pcam option) 2U-SEV (Zynq Utrascale- MPSoC Development Board) 15 Wilnk Virtex-7 FPGA VC707 Evaluation Kit Universal Programmer (Keltek Superpro 610p or equivalent) Zigbee module with antenna (KBee S2C Zigbee (Wire Antenna) or equivalent) Lot #8: Intelligent Biomedical Lab BIOPAC (Data Acquisition System for Biomedical Engineering) Freestyle Libre 2 Reader with Sensor Continuous Glucose Monitor (Starter Pack) My gesture control armband Myoware 2.0 Muscle Sensor Development Kit S 2.2 Inch Flex Sensor MySignals HW BLE Complete Kit (eHealth Medical Development Platform for Arduino) Lot #9: Computer Vision Lab | | - | | | |
| ZedBoard Advanced Image Processing Kit (Quad Pcam option) ZU-SEV (Zynq Ildrascalect MPSoC Development Board) Zilfascalect MPSoC Development Board) Zilfascalect MPSoC Development Board) Zilfascalect MPSoC Development Board) Zilfascalect MPSoC Development Zilfascalect MPSoC Zilfascalec | 12 | SoC Development Board with SYZYGY- | | | |
| 14 Ultrascale+ MPSoC Development Board) 15 Victory Tevaluation Kit 16 Victor Evaluation Kit 16 Universal Programmer (Kettek Superpro 610p or equivalent) 2 Zigbee module with antenna (XBee 52C Zigbee (Wire Antenna) or equivalent) 17 LOT #7: Furniture for Labs - Chairs 1. Chairs Lot #8: intelligent Biomedical Lab 1 BIOPAC (Data Acquisition System for Biomedical Engineering) 2 Freestyle Libre 2 Reader with Sensor - Continuous Glucose Monitor (Starter Pack) 3 Myo gesture control armband 4 Sensor Development Kit 5 2.2 Inch Flex Sensor MySignals HW BLE Complete Kit (eHealth Medical Development Platform for Arduino) Lot #9: Computer Vision Lab 1 Jetson Orin Nano Developer Kit 2 Jetson AGX Orin 64GB Developer Kit | 13 | ZedBoard Advanced Image Processing Kit (Quad Pcam option) | | | |
| 15 VC707 Evaluation Kit 16 Universal Programmer (Xeltek Superpro 610p or equivalent) 21 Zigbee module with antenna (Xee 52C 2 ZigBee (Wire Antenna) or equivalent) 17 LOT #7: Furniture for Labs - Chairs 1. Chairs 1. Chairs Lot #8: Intelligent Biomedical Lab 1 BIOPAC (Data Acquisition System for Biomedical Engineering) Freestyle Libre 2 Reader with Sensor - Continuous Glucose Monitor (Starter Pack) 3 Myo gesture control armband 4 MyoWare 2.0 Muscle Sensor Development Kit 5 2.2 Inch Flex Sensor MySignals HW BLE Complete Kit (eHealth Medical Development Platform for Arduino) Lot #9: Computer Vision Lab 1 Jetson Orin Nano Developer Kit 2 Jetson AGX Orin 64GB Developer Kit | 14 | Ultrascale+ MPSoC | | | |
| 16 (Xeltek Superpro 610p or equivalent) 27 | 15 | | | | |
| 17 antenna (XBee S2C ZigBee (Wire Antenna) or equivalent) LOT #7: Furniture for Labs - Chairs 1. Chairs Lot #8: Intelligent Biomedical Lab BIOPAC (Data Acquisition System for Biomedical Engineering) Freestyle Libre 2 Reader with Sensor - Continuous Glucose Monitor (Starter Pack) 3 Myo gesture control armband 4 MyoWare 2.0 Muscle Sensor Development Kit 5 2.2 Inch Flex Sensor MySignals HW BLE Complete Kit (eHealth Medical Development Platform for Arduino) Lot #9: Computer Vision Lab 1 Jetson Orin Nano Developer Kit 2 Jetson AGX Orin 64GB Developer Kit | 16 | (Xeltek Superpro 610p | | | |
| Lot #8: Intelligent Biomedical Lab BiOPAC (Data Acquisition System for Biomedical Engineering) Freestyle Libre 2 Reader with Sensor - Continuous Glucose Monitor (Starter Pack) Myo gesture control armband MyoWare 2.0 Muscle Sensor Development Kit S 2.2 Inch Flex Sensor MySignals HW BLE Complete Kit (eHealth Medical Development Platform for Arduino) Lot #9: Computer Vision Lab 1 Jetson Orin Nano Developer Kit 2 Jetson AGX Orin 64GB Developer Kit | 17 | antenna (XBee S2C ZigBee (Wire Antenna) | | | |
| Lot #8: Intelligent Biomedical Lab BIOPAC (Data Acquisition System for Biomedical Engineering) Freestyle Libre 2 Reader with Sensor - Continuous Glucose Monitor (Starter Pack) Myo gesture control armband Myoware 2.0 Muscle Sensor Development Kit 5 2.2 Inch Flex Sensor MySignals HW BLE Complete Kit (eHealth Medical Development Platform for Arduino) Lot #9: Computer Vision Lab 1 Jetson Orin Nano Developer Kit 2 Jetson AGX Orin 64GB Developer Kit | | | LOT #7: Furn | iture for Labs - Chairs | |
| BIOPAC (Data Acquisition System for Biomedical Engineering) Freestyle Libre 2 Reader with Sensor - Continuous Glucose Monitor (Starter Pack) Myo gesture control armband MyoWare 2.0 Muscle Sensor Development Kit 5 2.2 Inch Flex Sensor MySignals HW BLE Complete Kit (eHealth Medical Development Platform for Arduino) Lot #9: Computer Vision Lab 1 Jetson Orin Nano Developer Kit 2 Jetson AGX Orin 64GB Developer Kit | 1. | Chairs | | | |
| Acquisition System for Biomedical Engineering) Freestyle Libre 2 Reader with Sensor - Continuous Glucose Monitor (Starter Pack) Myo gesture control armband MyoWare 2.0 Muscle Sensor Development Kit 5 2.2 Inch Flex Sensor MySignals HW BLE Complete Kit (eHealth Medical Development Platform for Arduino) Lot #9: Computer Vision Lab 1 Jetson Orin Nano Developer Kit 2 Jetson AGX Orin 64GB Developer Kit | | | Lot #8: Intel | ligent Biomedical Lab | |
| 2 Reader with Sensor - Continuous Glucose Monitor (Starter Pack) 3 Myo gesture control armband MyoWare 2.0 Muscle Sensor Development Kit 5 2.2 Inch Flex Sensor MySignals HW BLE Complete Kit (eHealth Medical Development Platform for Arduino) Lot #9: Computer Vision Lab 1 Jetson Orin Nano Developer Kit 2 Jetson AGX Orin 64GB Developer Kit | 1 | Acquisition System for Biomedical | | | |
| armband MyoWare 2.0 Muscle Sensor Development Kit 5 2.2 Inch Flex Sensor MySignals HW BLE Complete Kit (eHealth Medical Development Platform for Arduino) Lot #9: Computer Vision Lab 1 Jetson Orin Nano Developer Kit 2 Jetson AGX Orin 64GB Developer Kit | 2 | Reader with Sensor - Continuous Glucose | | | |
| 4 Sensor Development Kit 5 2.2 Inch Flex Sensor MySignals HW BLE Complete Kit (eHealth Medical Development Platform for Arduino) Lot #9: Computer Vision Lab 1 Jetson Orin Nano Developer Kit 2 Jetson AGX Orin 64GB Developer Kit | 3 | | | | |
| MySignals HW BLE Complete Kit (eHealth Medical Development Platform for Arduino) Lot #9: Computer Vision Lab 1 Jetson Orin Nano Developer Kit 2 Jetson AGX Orin 64GB Developer Kit | 4 | Sensor Development | | | |
| Complete Kit (eHealth Medical Development Platform for Arduino) Lot #9: Computer Vision Lab 1 Jetson Orin Nano Developer Kit 2 Jetson AGX Orin 64GB Developer Kit | 5 | 2.2 Inch Flex Sensor | | | |
| 1 Jetson Orin Nano Developer Kit 2 Jetson AGX Orin 64GB Developer Kit | 6 | Complete Kit (eHealth Medical Development Platform for | | | |
| Developer Kit Jetson AGX Orin 64GB Developer Kit | | | Lot #9: Co | mputer Vision Lab | |
| Developer Kit | 1 | | | | |
| 3 Jetson TX2 NX Module | 2 | | | | |
| | 3 | Jetson TX2 NX Module | | | |

Form G: Price Schedule Form

(To be Submitted in a separate and sealed envelope duly marked as Financial Proposal)

| Name of Bidder: | [Insert Name of Bidder] | Date: | Select date |
|-----------------|--------------------------|-------|-------------|
| ITB reference: | PAF: IAST-AIE-ITB-114-21 | | |

[The Bidder is required to prepare the Price Schedule following the below format. The Price Schedule must include a detailed cost breakdown of all goods and related services to be provided.]

We, the <<Name of Bidder>>, hereby submit our Financial Bid for the Supply of Items as below. We assure you of our full compliance to the required specifications, delivery schedule and other terms without any deviation and/or reservations. We reiterate our acceptance to the terms and conditions of the RFP. Our Financial proposal as below is submitted for your kind consideration;

QUOTE PRICE IN PKR

| | Quoted Items in compliance to the Technical Specifications as referred in Section – 5a and Section – 5b | Quantity | Unit Price [in Rs. PKR] | GST [in Rs. PKR] | Total Price [in Rs. In Million PKR] |
|----|--|---------------|----------------------------|---------------------|--|
| | | Lot 1 Customi | zed Multi-copters | Agile Drone | |
| 1. | Custom-Build Agile Multi-copter | 1 | | | |
| 2. | RTK-GNSS Base station (Here+V2 or Equivalent) | 1 | | | |
| 3. | Extra Aerial & Ground Batteries | 1 | | | |
| | L | ot 2 Customiz | ed Multi-copters | Carrier Drone | |
| 1. | Custom-Built Carrier Multi-copter | 1 | | | |
| 2. | RTK-GNSS Base station (Here+V2 or Equivalent) | 1 | | | |
| 3. | Extra Aerial & Ground Batteries | 1 | | | |
| | | | | | |
| | | LOT #3: Dro | ne Swarm and S | Safety Net | |
| 1. | Flame-Retardant Drone Safety Net (Custom-Made) 30 x 100 Feet | 1 | | | |
| 2. | Flame-Retardant Drone Safety Net (Custom-Made) 25 x 25 Feet | 1 | | | |
| 3. | Loco swarm bundle inclusive additional highlighted accessories | 2 | | | |

| 4. | Drone DJI Mavic 3 Pro | 1 | | | |
|----|--|--------------|--------------------|----------|--|
| | or equivalent | Lot # | 4: Field Robotics | Lah | |
| | Unmanned ground | LOC # | -4. Field Robotics | Lau | |
| 1 | vehicle: [Segway RMPLite 220 or equivalent] | 1 | | | |
| 2 | Modern Manipulator Arm QArm – Quanser or Equivalent | 1 | | | |
| | | Lot #5: IoT, | , Sensors and IT E | quipment | |
| 1 | Arduino Edge Control | 10 | | | |
| 2 | Arduino Explore IoT Kit | 10 | | | |
| 3 | EMoRo 2560 Controller | 10 | | | |
| 4 | ARDUINO UNO WIFI REV2 | 10 | | | |
| 5 | USB 2.0 Cable Type A/B | 20 | | | |
| 6 | Soldering Stand: QuadHands Classic Helping Hands Tool | 2 | | | |
| 7 | High Precision Barometric Pressure Sensor Grove(DPS310) or equivalent | 10 | | | |
| 8 | Gravity: UART Infrared CO2 Sensor (0- 50000ppm) | 1 | | | |
| 9 | Grove - Gas Sensor (MQ3) | 10 | | | |
| 10 | Gravity: Analog CO2 Gas Sensor (MG-811 Sensor) | 10 | | | |
| 11 | Gravity: Analog Capacitive Soil Moisture Sensor - Corrosion Resistant | 30 | | | |
| 12 | Digital Infrared Temperature Sensor (Grove or equivalent) | 10 | | | |
| 13 | Multi-function Environmental Module - CCS811+BME280 | 10 | | | |
| 14 | Gravity: Non-contact Digital Water / Liquid Level Sensor For Arduino | 20 | | | |
| 15 | Air Quality Sensor (CCS811 DFRobot or equivalent) | 20 | | | |
| 16 | Water Sensor (Grove or equivalent) | 20 | | | |

| 17 | Temperature Sensor | 20 | | |
|----|---|----|--|--|
| | (Grove or equivalent) | | | |
| 18 | Temp & Humidity & Barometer Sensor (BME280 Grove or equivalent) | 10 | | |
| 19 | Moisture Sensor (Grove or equivalent) | 20 | | |
| 20 | Hall Sensor (Grove or equivalent) | 10 | | |
| 21 | Analog pH Sensor / Meter Pro Kit For Arduino (Gravity or equivalent) | 10 | | |
| 22 | Ozone Sensor (0- 10ppm) (Gravity or equivalent) | 10 | | |
| 23 | SOIL HUMIDITY SENSOR, WATERMARK 2 M / 75 CM (Pack of 6) | 10 | | |
| 24 | Arduino Nano 33 IoT with headers | 10 | | |
| 25 | WiFi Module - ESP8266 (4MB Flash) | 20 | | |
| 26 | ESP-01S Wifi Module with relay or equivalent | 20 | | |
| 27 | Fingerprint Sensor Module (Adafruit or equivalent) | 10 | | |
| 28 | Adafruit DS1307 Real Time Clock Assembled Breakout Board | 10 | | |
| 29 | DS3231 Precision RTC Breakout (Adafruit or equivalent) | 5 | | |
| 30 | MicroSD card breakout board+(Adafruit or equivalent) | 10 | | |
| 31 | HDMI Cables for Raspberry Pi 4 B+ (Micro HDMI to HDMI) | 30 | | |
| 32 | Hot Air Soldering Rework Station w/ Three Nozzles – Quick 957DW+ | 2 | | |
| 33 | Engineer Professional Silicone-Tip Solder Sucker | 2 | | |
| 34 | ATTEN 80W 110V Soldering Iron With Station - ST-2090D | 6 | | |
| 35 | 128 GB Extreme microSDHC UHS-I | 40 | | |

| | Memory Card with Adapter or equivalent | | | | |
|----|--|--------|------------------|-----|--|
| 36 | Wire Stripper | 2 | | | |
| 37 | Breadboard power supply | 10 | | | |
| 38 | Vero Board | 20 | | | |
| 39 | Magnifying glass for soldering | 5 | | | |
| 40 | Breadboard | 20 | | | |
| 41 | RAM - 16GB DDR4 3200MHz SODIMM PC4-25600 | 12 | | | |
| 42 | SATA 2.5" SSD 512GB for laptops | 10 | | | |
| 43 | Keyboards | 30 | | | |
| | | Lot #6 | 6: Embedded Syst | ems | |
| 1 | WiFi LoRa 32 Dev Board (Heltec or equivalent) | 10 | | | |
| 2 | LoRa Test Board Kit (LLCC68 based E220- 900T30S or equivalent) | 2 | | | |
| 3 | LoRa LLCC68 Development Kit 430 MHz 470 MHz | 2 | | | |
| 4 | LLCC68 LoRa Module 868MHz 915MHz 30dBm UART | 10 | | | |
| 5 | LLCC68 LoRa Module 433MHz 470MHz 30dBm UART | 10 | | | |
| 6 | Antenna for LLCC68 LoRa Module 868MHz 915MHz 30dBm UART | 10 | | | |
| 7 | DE1-SoC Development Kit including cables and power adapter | 2 | | | |
| 8 | DE10 Lite | 10 | | | |
| 9 | Super Value Ultimate 37 in 1 Sensor Modules Kit for Arduino & MCU | 8 | | | |
| 10 | ZedBoard Zynq-7000 ARM/FPGA SoC Development Board | 8 | | | |
| 11 | PYNQ-Z1: Python Productivity for Zynq- 7000 ARM/FPGA SoC with Accessory Kit | 8 | | | |
| 12 | Eclypse Z7: Zynq-7000 SoC Development Board with SYZYGY- compatible Expansion | 1 | | | |

| | ZadDaaud Advanced | | | | | |
|----|--|------------|--------------------|----------|--|--|
| 42 | ZedBoard Advanced | - | | | | |
| 13 | Image Processing Kit (Quad Pcam option) | 5 | | | | |
| | | | | | | |
| 14 | ZU-5EV (Zynq Ultrascale+ MPSoC | 1 | | | | |
| 14 | Development Board) | 1 | | | | |
| | Xilinx Virtex-7 FPGA | | | | | |
| 15 | VC707 Evaluation Kit | 1 | | | | |
| | Universal Programmer | | | | | |
| 16 | (Xeltek Superpro 610p | 5 | | | | |
| 10 | or equivalent) | 3 | | | | |
| | Zigbee module with | | | | | |
| | antenna (XBee S2C | | | | | |
| 17 | ZigBee (Wire Antenna) | 10 | | | | |
| | or equivalent) | | | | | |
| | or equivalent, | LOT #7: E | urniture for Labs | - Chairs | | |
| - | | | l lintare for Labs | - Chans | | |
| 1. | Chairs | 40 | | | | |
| | | Lot #8: Ir | ntelligent Biomed | ical Lab | | |
| | BIOPAC (Data | | | | | |
| 1 | Acquisition System for | 1 | | | | |
| _ | Biomedical | _ | | | | |
| | Engineering) | | | | | |
| | Freestyle Libre 2 | | | | | |
| 2 | Reader with Sensor - | 2 | | | | |
| | Continuous Glucose | | | | | |
| | Monitor (Starter Pack) | | | | | |
| 3 | Myo gesture control armband | 2 | | | | |
| | MyoWare 2.0 Muscle | | | | | |
| 4 | Sensor Development | 2 | | | | |
| 4 | Kit | 2 | | | | |
| 5 | 2.2 Inch Flex Sensor | 20 | | | | |
| , | | 20 | | | | |
| | MySignals HW BLE | | | | | |
| | Complete Kit | | | | | |
| 6 | (eHealth Medical | 1 | | | | |
| | Development | | | | | |
| | Platform for | | | | | |
| | Arduino) | | | | | |
| | Lot #9: Computer Vision Lab | | | | | |
| 1 | Jetson Orin Nano | 4 | | | | |
| _ | Developer Kit | - | | | | |
| 2 | Jetson AGX Orin 64GB | 4 | | | | |
| | Developer Kit | | | | | |
| 3 | Jetson TX2 NX Module | 4 | | | | |

Extended Warranty Price (at discretion of PAF-IAST)

QUOTE PRICE IN PKR

| | | | | - sh - |
|----|--|-------------------------------|-------------------------------|-------------------------------|
| | Quoted Items in compliance to the Technical Specifications as referred in Section – 5a and Section – 5b | 2 nd Year (PKR) | 3 rd Year (PKR) | 4 th Year (PKR) |
| | Section – 50 | | | |
| | Lot 1 Customized I | Multi-copters Agi | le Drone | |
| 1. | Custom-Build Agile Multi-copter | | | |
| 3. | RTK-GNSS Base station (Here+V2 or Equivalent) | | | |
| 4. | Extra Aerial & Ground Batteries | | | |
| | Lot 2 Customized N | Aulti-copters Carr | ier Drone | |
| 2. | Custom-Built Carrier Multi-copter | | | |
| 3. | RTK-GNSS Base station (Here+V2 or Equivalent) | | | |
| 4. | Extra Aerial & Ground Batteries | | | |
| | LOT #3: Drone S | Swarm and Safe | ty Net | |
| 1. | Flame-Retardant Drone Safety Net (Custom-Made) 30 x 100 Feet | | | |
| 2. | Flame-Retardant Drone Safety Net (Custom-Made) 25 x 25 Feet | | | |
| 3. | Loco swarm bundle inclusive additional highlighted accessories | | | |
| 4. | Drone DJI Mavic 3 Pro or equivalent | | | |
| | Lot #4: Fi | eld Robotics Lab | | |
| 1 | Unmanned ground vehicle: [Segway RMPLite 220 or equivalent] | | | |
| 2 | Modern Manipulator Arm QArm – Quanser or Equivalent | | | |
| | Lot #5: IoT, Sen | sors and IT Equip | ment | |
| 1 | Arduino Edge Control | | | |
| 2 | Arduino Explore IoT Kit | | | |
| 3 | EMoRo 2560 Controller | | | |
| 4 | ARDUINO UNO WiFi REV2 | | | |
| 5 | USB 2.0 Cable Type A/B | | | |

| | 1 | | |
|----|---|--|--|
| 6 | Soldering Stand : QuadHands Classic Helping Hands Tool | | |
| 7 | High Precision Barometric Pressure Sensor Grove(DPS310) or equivalent | | |
| 8 | Gravity: UART Infrared CO2 Sensor (0-50000ppm) | | |
| 9 | Grove - Gas Sensor (MQ3) | | |
| 10 | Gravity: Analog CO2 Gas Sensor (MG-811 Sensor) | | |
| 11 | Gravity: Analog Capacitive Soil Moisture Sensor - Corrosion Resistant | | |
| 12 | Digital Infrared Temperature Sensor (Grove or equivalent) | | |
| 13 | Multi-function Environmental Module - CCS811+BME280 | | |
| 14 | Gravity: Non-contact Digital Water / Liquid Level Sensor For Arduino | | |
| 15 | Air Quality Sensor (CCS811 DFRobot or equivalent) | | |
| 16 | Water Sensor (Grove or equivalent) | | |
| 17 | Temperature Sensor (Grove or equivalent) | | |
| 18 | Temp & Humidity & Barometer Sensor (BME280 Grove or equivalent) | | |
| 19 | Moisture Sensor (Grove or equivalent) | | |
| 20 | Hall Sensor (Grove or equivalent) | | |
| 21 | Analog pH Sensor / Meter Pro Kit For Arduino (Gravity or equivalent) | | |
| 22 | Ozone Sensor (0-10ppm) (Gravity or equivalent) | | |
| 23 | SOIL HUMIDITY SENSOR, WATERMARK 2 M / 75 CM (Pack of 6) | | |
| 24 | Arduino Nano 33 IoT with headers | | |
| 25 | WiFi Module - ESP8266 (4MB Flash) | | |
| 26 | ESP-01S Wifi Module with relay or equivalent | | |
| 27 | Fingerprint Sensor Module (Adafruit or equivalent) | | |
| 28 | Adafruit DS1307 Real Time Clock Assembled Breakout Board | | |
| 29 | DS3231 Precision RTC Breakout (Adafruit or equivalent) | | |
| 30 | MicroSD card breakout board+(Adafruit or equivalent) | | |

| 31 | HDMI Cables for Raspberry Pi 4 B+ (Micro HDMI to HDMI) | | | |
|----|--|-----------------|---|--|
| 32 | Hot Air Soldering Rework Station w/ Three Nozzles – Quick 957DW+ | | | |
| 33 | Engineer Professional Silicone-Tip Solder Sucker | | | |
| 34 | ATTEN 80W 110V Soldering Iron With Station - ST-2090D | | | |
| 35 | 128 GB Extreme microSDHC UHS-I Memory Card with Adapter or equivalent | | | |
| 36 | Wire Stripper | | | |
| 37 | Breadboard power supply | | | |
| 38 | Vero Board | | | |
| 39 | Magnifying glass for soldering | | | |
| 40 | Breadboard | | | |
| 41 | RAM - 16GB DDR4 3200MHz SODIMM PC4-25600 | | | |
| 42 | SATA 2.5" SSD 512GB for laptops | | | |
| 43 | Keyboards | | | |
| | Lot #6: Em | nbedded Systems | ; | |
| 1 | WiFi LoRa 32 Dev Board (Heltec or equivalent) | | | |
| 2 | LoRa Test Board Kit (LLCC68 based E220-900T30S or equivalent) | | | |
| 3 | LoRa LLCC68 Development Kit 430 MHz 470 MHz | | | |
| 4 | LLCC68 LoRa Module 868MHz 915MHz 30dBm UART | | | |
| 5 | LLCC68 LoRa Module 433MHz 470MHz 30dBm UART | | | |
| 6 | Antenna for LLCC68 LoRa Module 868MHz 915MHz 30dBm UART | | | |
| 7 | DE1-SoC Development Kit including cables and power adapter | | | |
| 8 | DE10 Lite | | | |
| 9 | Super Value Ultimate 37 in 1 Sensor Modules Kit for Arduino & MCU | | | |
| 10 | ZedBoard Zynq-7000 ARM/FPGA SoC Development Board | | | |
| 11 | PYNQ-Z1: Python Productivity for Zynq-7000 ARM/FPGA SoC with Accessory Kit | | | |
| 12 | Eclypse Z7: Zynq-7000 SoC Development Board with SYZYGY- compatible Expansion | | | |

| | | | ı | |
|------------------------------------|--|--------------------|------|--|
| 13 | ZedBoard Advanced Image Processing Kit (Quad Pcam option) | | | |
| 14 | ZU-5EV (Zynq Ultrascale+ MPSoC Development Board) | | | |
| 15 | Xilinx Virtex-7 FPGA VC707 Evaluation Kit | | | |
| 16 | Universal Programmer (Xeltek Superpro 610p or equivalent) | | | |
| 17 | Zigbee module with antenna (XBee S2C ZigBee (Wire Antenna) or equivalent) | | | |
| | LOT #7: Furni | ture for Labs - Ch | airs | |
| 1. | Chairs | | | |
| Lot #8: Intelligent Biomedical Lab | | | | |
| 1 | BIOPAC (Data Acquisition System for Biomedical Engineering) | | | |
| 2 | Freestyle Libre 2 Reader with Sensor - Continuous Glucose Monitor (Starter Pack) | | | |
| 3 | Myo gesture control armband | | | |
| 4 | MyoWare 2.0 Muscle Sensor Development Kit | | | |
| 5 | 2.2 Inch Flex Sensor | | | |
| 6 | MySignals HW BLE Complete Kit (eHealth Medical Development Platform for Arduino) | | | |
| Lot #9: Computer Vision Lab | | | | |
| 1 | Jetson Orin Nano Developer Kit | | | |
| 2 | Jetson AGX Orin 64GB Developer Kit | | | |
| 3 | Jetson TX2 NX Module | | | |

QUOTE PRICE IN PKR

| Total Bid Value in Figures (including | ng Extended Warranty Price): PKR | |
|---|--|--|
| Total Bid Value in words (including | g Extended Warranty Price): PKR | |
| | | |
| Offered Percentage Discount in ca | ase LC (Letter of Credit) is opted as Mode of Payment: | |
| | | |
| Final Bid Value in Figures (including | ng Extended Warranty & Discount): | |
| Final Bid Value in words (including | g Extended Warranty & Discount): | |
| | | |
| Name & Designation of Authorized P | erson: | |
| Signature: | (Please affix company stamp here) | |
| Note: Quoted price must be inclusive of all taxes and duties. | | |

Annex – I: Integrity Pact

The Bidders will be required to submit the below text on stamp paper after filling in the details and duly signed as well as stamped, as part of their Technical Proposal.

DECLARATION OF FEES, COMMISSION AND BROKERAGE ETC PAYABLE BY THE SUPPLIER OF GOODS, SERVICES & WORK IN CONTRACTS WORTH RS. 10.0 MILLION OR MORE

| (To be filled by the bidder as a part of technical | |
|--|---|
| Contract Number: | |
| Contract Value: | |
| Contract Title: | |
| contract, right, interest, privilege or o | that it has not obtained or induced the procurement of any other obligation or benefit from Government of Pakistan or any hereof or any other entity owned or controlled by it (GoP) through |
| fully declared the brokerage, commiss or agreed to give and shall not give or or indirectly through any nature or judgments, director, promoter, shareh finder's fee or kickback, whether descriptions inducing the procurement of a column. | forgoing, represents and warrants that it has ion, fees etc. paid or payable to anyone and not given or not given agree to give to anyone within or outside Pakistan either directly juridical person, including its affiliate, agent, associate, broker, nolder, sponsor or subsidiary, any commission, gratification, bribe, ribed as consultant fee or otherwise, with the object of obtaining ntract, right, interest, privilege or other obligation or benefit in has been expressly declared pursuant hereto. |
| arrangements with all persons in resp | has made and will make full disclosure of all agreements and pect of or related to the transaction with GoP and has not taken to circumvent the above declaration, representation or warranty. |
| making full discloser, misrepresenting declaration, representation and warra obligation or benefit obtained or proc | nsibility and strict liability for making any false declaration, not g facts or taking any action likely to defeat the purpose of this anty. It agrees that any contract, right, interest, privilege or other cured as aforesaid shall, without prejudice to any other right and law, contract or other instrument, be voidable at the option of |
| identify GoP for any loss or damage further pay compensation to GoP in gratification, bribe, finder's fee or kick | dies exercised by GoP in this regard, agrees to incurred by it on account of its corrupt business practices and an amount equivalent to ten time the sum of any commission, kback given by as aforesaid for the purpose of int of any contract, right, interest, privilege or other obligation or |
| Buyer] [Seller / Supplier] | |

Annex – II: Draft Contract Sample

Available at PAF: IAST website at http://www.paf-iast.edu.pk/downloads